

## INA226 高侧/低侧测量、 双向电流/功率监视器，具有 I<sup>2</sup>C 兼容接口

### 1 特性

- 感测的总线电压范围：0V 至 36V
- 高侧或低侧感测
- 报告电流、电压和功率
- 高精度：
  - 0.1% 增益误差（最大值）
  - 10 $\mu$ V 偏移（最大值）
- 可配置的取平均值选项
- 16 个可编程地址
- 由 2.7V 至 5.5V 电源供电
- 10 引脚 DGS 超薄小外形尺寸 (VSSOP) 封装

### 2 应用范围

- 服务器
- 电信设备
- 计算
- 电源管理
- 电池充电器
- 电源
- 测试设备

### 3 说明

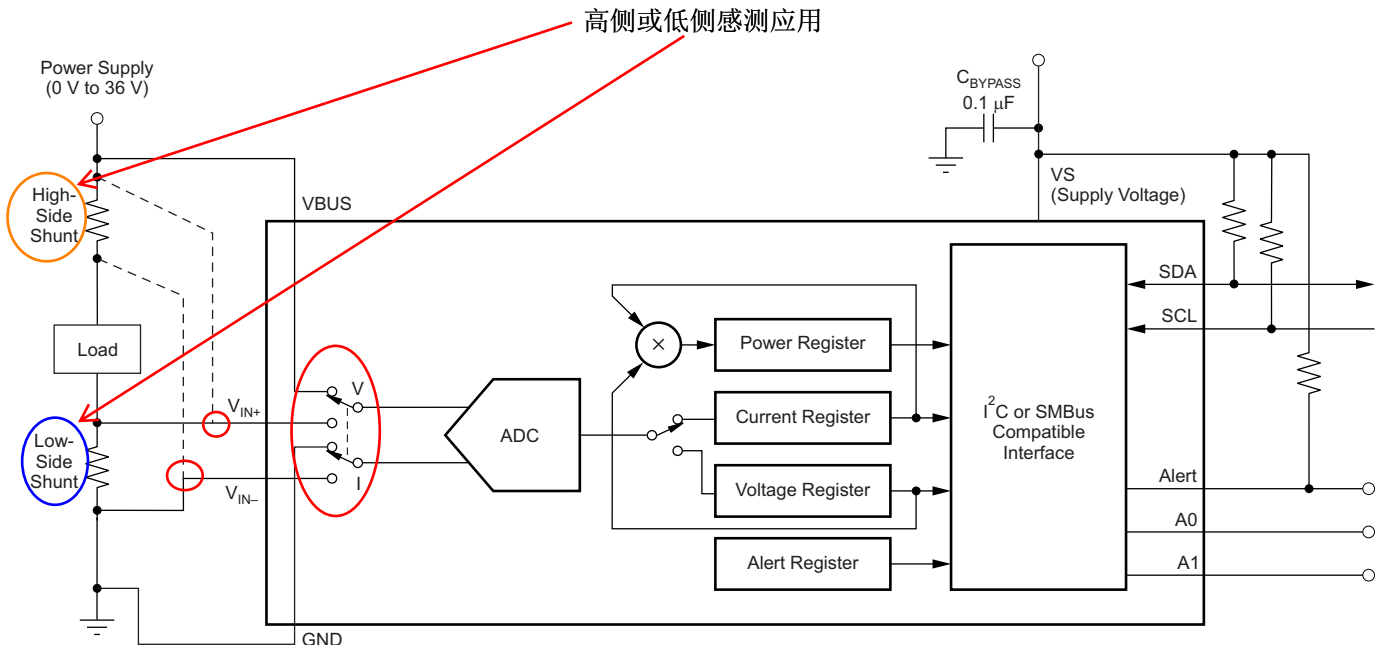
INA226 是一款分流/功率监视器，具有 I<sup>2</sup>C™ 或 SMBUS 兼容接口。该器件监视分流压降和总线电源电压。可编程校准值、转换时间和取平均值功能与内部乘法器相结合，可实现电流值（单位为安培）和功率值（单位为瓦）的直接读取。

INA226 可在 0V 至 36V 的共模总线电压范围内感测电流，与电源电压无关。该器件由一个 2.7V 至 5.5V 的单电源供电，电源电流典型值为 330 $\mu$ A。该器件的额定工作温度范围为 -40°C 至 125°C，I<sup>2</sup>C 兼容接口上具有多达 16 个可编程地址。

器件信息<sup>(1)</sup>

器件型号	封装	封装尺寸（标称值）
INA226	VSSOP (10)	3.00mm x 3.00mm

(1) 如需了解所有可用封装，请见数据表末尾的可订购产品附录。



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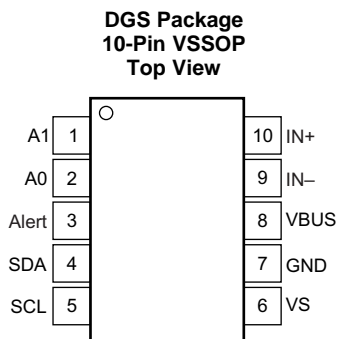
## 4 修订历史记录

### Changes from Original (June 2011) to Revision A

Page

- 已添加 处理额定值表，特性描述部分，器件功能模式，应用和实施部分，电源相关建议部分，布局部分，器件和文档支持部分以及机械、封装和可订购信息部分 ..... 1

## 5 Pin Configuration and Functions



### Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
A0	2	Digital input	Address pin. Connect to GND, SCL, SDA, or VS. 表 2 shows pin settings and corresponding addresses.
A1	1	Digital input	Address pin. Connect to GND, SCL, SDA, or VS. 表 2 shows pin settings and corresponding addresses.
Alert	3	Digital output	Multi-functional alert, open-drain output.
GND	7	Analog	Ground.
IN+	10	Analog input	Connect to supply side of shunt resistor.
IN-	9	Analog input	Connect to load side of shunt resistor.
SCL	5	Digital input	Serial bus clock line, open-drain input.
SDA	4	Digital I/O	Serial bus data line, open-drain input/output.
VBUS	8	Analog input	Bus voltage input.
VS	6	Analog	Power supply, 2.7 V to 5.5 V.

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>VS</sub>	Supply voltage		6	V
Analog Inputs, IN+, IN–	Differential (V <sub>IN+</sub> – V <sub>IN–</sub> ) <sup>(2)</sup>	–40	40	V
	Common-Mode (V <sub>IN+</sub> + V <sub>IN–</sub> ) / 2	–0.3	40	
V <sub>VBUS</sub>		–0.3	40	V
V <sub>SDA</sub>		GND – 0.3	6	V
V <sub>SCL</sub>		GND – 0.3	V <sub>VS</sub> + 0.3	V
I <sub>IN</sub>	Input current into any pin		5	mA
I <sub>OUT</sub>	Open-drain digital output current		10	mA
T <sub>J</sub>	Junction temperature		150	°C
T <sub>stg</sub>	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) IN+ and IN– may have a differential voltage between –40 V and 40 V. However, the voltage at these pins must not exceed the range –0.3 V to 40 V.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge		
	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	±2500	V
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±1000	
	Machine model (MM)	±150	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V <sub>CM</sub>	Common-mode input voltage		12		V
V <sub>VS</sub>	Operating supply voltage		3.3		V
T <sub>A</sub>	Operating free-air temperature	–40		125	°C

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		INA226	UNIT
		DGS (VSSOP)	
		10 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	171.4	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	42.9	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	91.8	°C/W
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	1.5	°C/W
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	90.2	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	n/a	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

$T_A = 25^\circ\text{C}$ ,  $V_{VS} = 3.3\text{ V}$ ,  $V_{IN+} = 12\text{ V}$ ,  $V_{SENSE} = (V_{IN+} - V_{IN-}) = 0\text{ mV}$  and  $V_{VBUS} = 12\text{ V}$ , unless otherwise noted

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
INPUT						
	Shunt voltage input range		−81.9175		81.92	mV
	Bus voltage input range <sup>(1)</sup>		0		36	V
CMRR	Common-mode rejection	0 V ≤ V <sub>IN+</sub> ≤ 36 V	126	140		dB
V <sub>OS</sub>	Shunt offset voltage, RTI <sup>(2)</sup>			±2.5	±10	μV
	Shunt offset voltage, RTI <sup>(2)</sup> vs temperature	−40°C ≤ T <sub>A</sub> ≤ 125°C		0.02	0.1	μV/°C
PSRR	Shunt offset voltage, RTI <sup>(2)</sup> vs Power supply	2.7 V ≤ VS ≤ 5.5 V		2.5		μV/V
V <sub>OS</sub>	Bus offset voltage, RTI <sup>(2)</sup>			±1.25	±7.5	mV
	Bus offset voltage, RTI <sup>(2)</sup> vs temperature	−40°C ≤ T <sub>A</sub> ≤ 125°C		10	40	μV/°C
PSRR	Bus offset voltage, RTI <sup>(2)</sup> vs power supply			0.5		mV/V
I <sub>B</sub>	Input bias current (I <sub>IN+</sub> , I <sub>IN−</sub> pins)			10		μA
	VBUS input impedance			830		kΩ
	Input leakage <sup>(3)</sup>	(IN+ pin) + (IN− pin), Power-down mode		0.1	0.5	μA
DC ACCURACY						
	ADC native resolution			16		Bits
	1 LSB step size	Shunt voltage		2.5		μV
		Bus voltage		1.25		mV
	Shunt voltage gain error			0.02%	0.1%	
	Shunt voltage gain error vs temperature	−40°C ≤ T <sub>A</sub> ≤ 125°C		10	50	ppm/°C
	Bus voltage gain error			0.02%	0.1%	
	Bus voltage gain error vs temperature	−40°C ≤ T <sub>A</sub> ≤ 125°C		10	50	ppm/°C
	Differential nonlinearity			±0.1		LSB
t <sub>CT</sub>	ADC conversion time	CT bit = 000		140	154	μs
		CT bit = 001		204	224	
		CT bit = 010		332	365	
		CT bit = 011		588	646	
		CT bit = 100		1.1	1.21	ms
		CT bit = 101		2.116	2.328	
		CT bit = 110		4.156	4.572	
		CT bit = 111		8.244	9.068	
SMBus						
	SMBus timeout <sup>(4)</sup>			28	35	ms

- (1) While the input range is 36 V, the full-scale range of the ADC scaling is 40.96 V. See the [Basic ADC Functions](#) section. Do not apply more than 36 V.
- (2) RTI = Referred-to-input.
- (3) Input leakage is positive (current flowing into the pin) for the conditions shown at the top of this table. Negative leakage currents can occur under different input conditions.
- (4) SMBus timeout in the INA226 resets the interface any time SCL is low for more than 28 ms.

**INA226**

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**Electrical Characteristics (接下页)**
 $T_A = 25^\circ\text{C}$ ,  $V_{VS} = 3.3\text{ V}$ ,  $V_{IN+} = 12\text{ V}$ ,  $V_{SENSE} = (V_{IN+} - V_{IN-}) = 0\text{ mV}$  and  $V_{VBUS} = 12\text{ V}$ , unless otherwise noted

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>DIGITAL INPUT/OUTPUT</b>						
Input capacitance				3		pF
Leakage input current		$0\text{ V} \leq V_{SCL} \leq V_{VS}$ , $0\text{ V} \leq V_{SDA} \leq V_{VS}$ , $0\text{ V} \leq V_{Alert} \leq V_{VS}$ , $0\text{ V} \leq V_{A0} \leq V_{VS}$ , $0\text{ V} \leq V_{A1} \leq V_{VS}$		0.1	1	$\mu\text{A}$
$V_{IH}$	High-level input voltage		$0.7 \times V_{VS}$		6	V
$V_{IL}$	Low-level input voltage		-0.5		$0.3 \times V_{VS}$	V
$V_{OL}$	Low-level output voltage, SDA, Alert	$I_{OL} = 3\text{ mA}$	0		0.4	V
Hysteresis				500		mV
<b>POWER SUPPLY</b>						
Operating supply range			2.7		5.5	V
$I_Q$	Quiescent current			330	420	$\mu\text{A}$
Quiescent current, power-down (shutdown) mode				0.5	2	$\mu\text{A}$
$V_{POR}$	Power-on reset threshold			2		V

## 6.6 Typical Characteristics

At  $T_A = 25^\circ\text{C}$ ,  $V_{VS} = 3.3\text{ V}$ ,  $V_{IN+} = 12\text{ V}$ ,  $V_{SENSE} = (V_{IN+} - V_{IN-}) = 0\text{ mV}$  and  $V_{VBUS} = 12\text{ V}$ , unless otherwise noted.

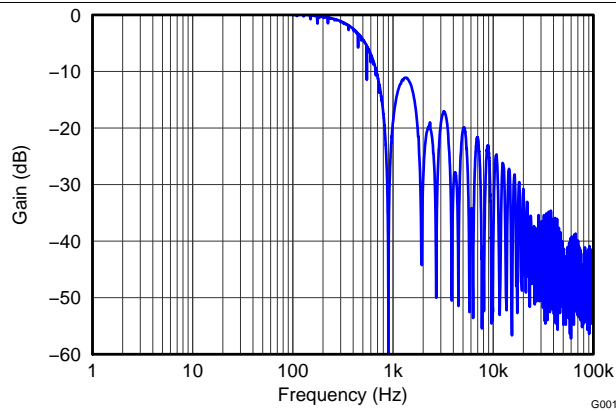


图 1. Frequency Response

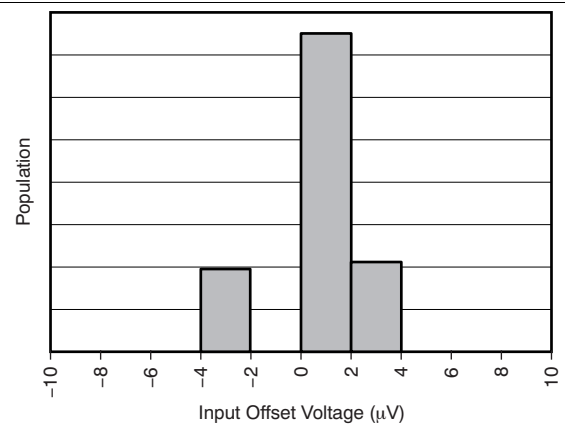


图 2. Shunt Input Offset Voltage Production Distribution

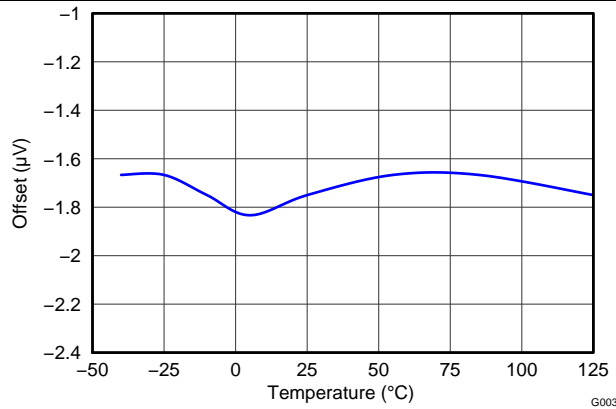


图 3. Shunt Input Offset Voltage vs Temperature

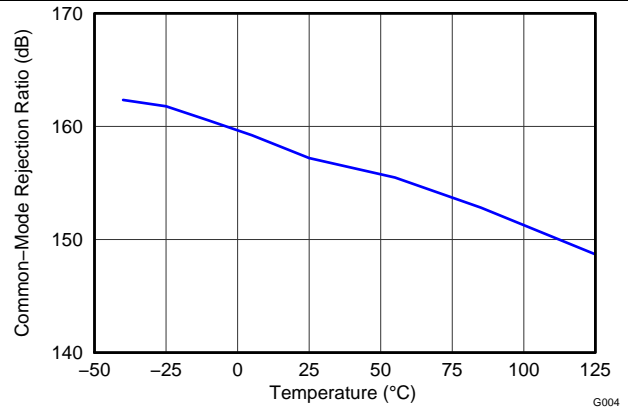


图 4. Shunt Input Common-Mode Rejection Ratio vs Temperature

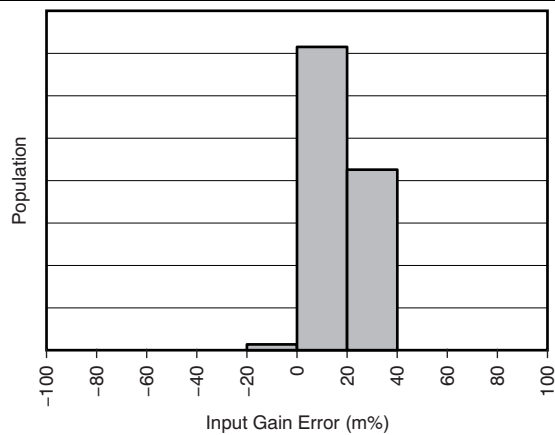


图 5. Shunt Input Gain Error Production Distribution

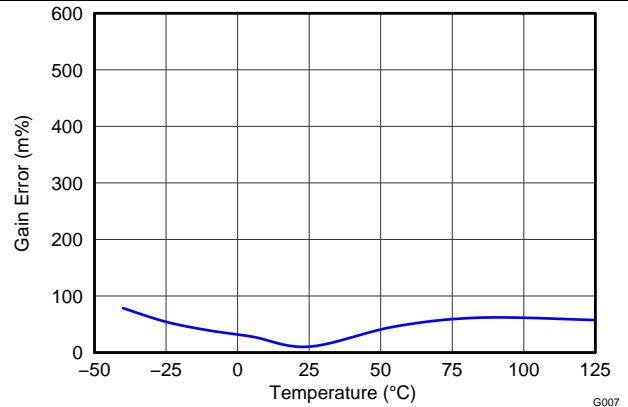


图 6. Shunt Input Gain Error vs Temperature

## Typical Characteristics (接下页)

At  $T_A = 25^\circ\text{C}$ ,  $V_{VS} = 3.3\text{ V}$ ,  $V_{IN+} = 12\text{ V}$ ,  $V_{SENSE} = (V_{IN+} - V_{IN-}) = 0\text{ mV}$  and  $V_{VBUS} = 12\text{ V}$ , unless otherwise noted.

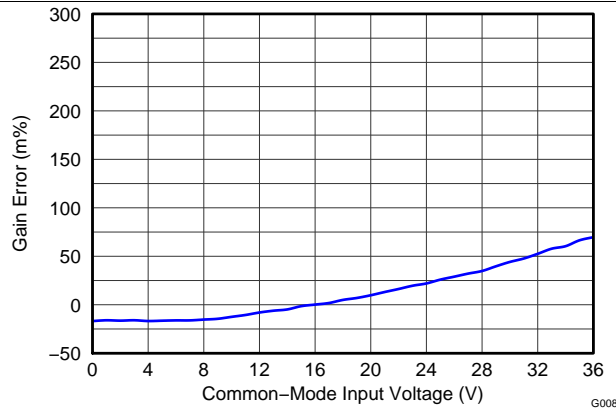


图 7. Shunt Input Gain Error vs Common-Mode Voltage

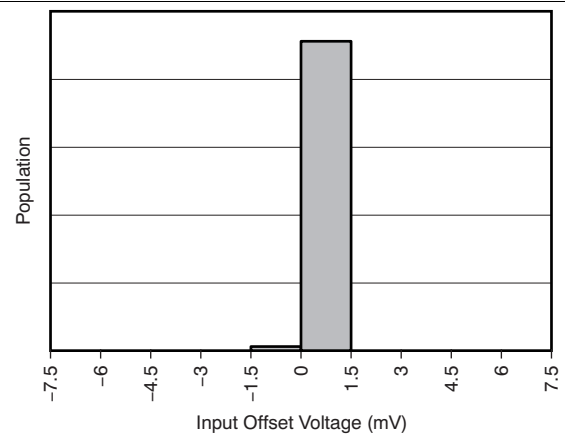


图 8. Bus Input Offset Voltage Production Distribution

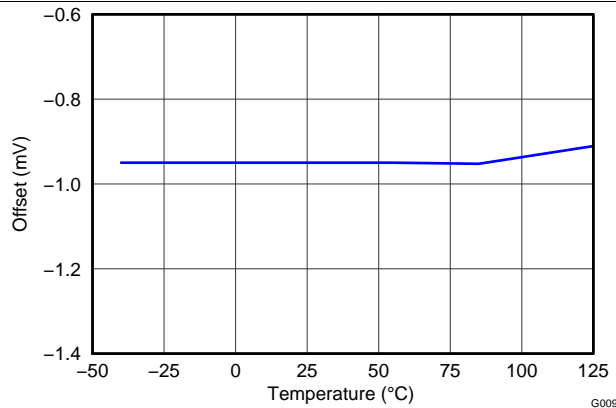


图 9. Bus Input Offset Voltage vs Temperature

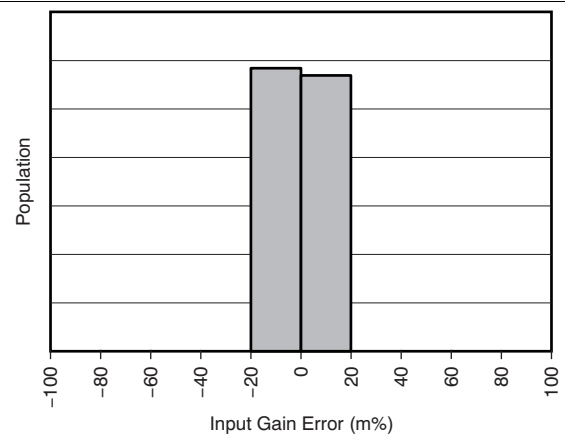


图 10. Bus Input Gain Error Production Distribution

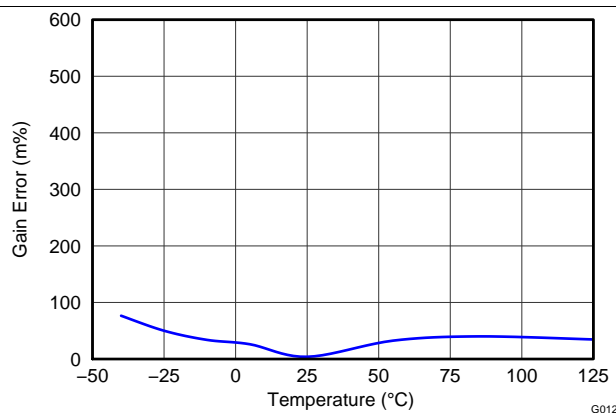


图 11. Bus Input Gain Error vs Temperature

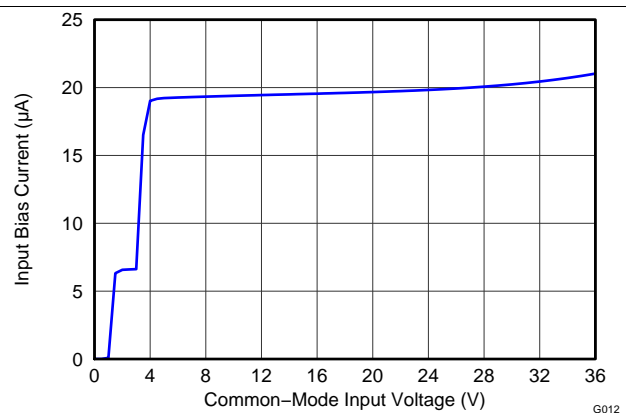


图 12. Input Bias Current vs Common-Mode Voltage



## Typical Characteristics (接下页)

At  $T_A = 25^\circ\text{C}$ ,  $V_{VS} = 3.3\text{ V}$ ,  $V_{IN+} = 12\text{ V}$ ,  $V_{SENSE} = (V_{IN+} - V_{IN-}) = 0\text{ mV}$  and  $V_{VBUS} = 12\text{ V}$ , unless otherwise noted.

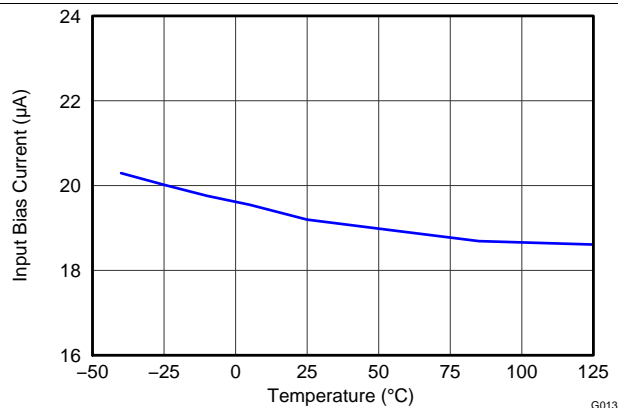


图 13. Input Bias Current vs Temperature

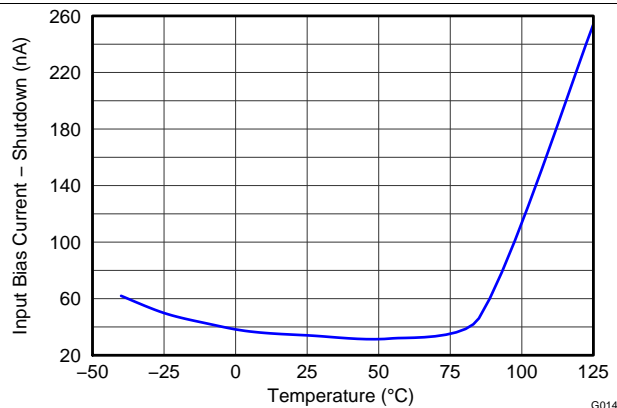


图 14. Input Bias Current vs Temperature, Shutdown

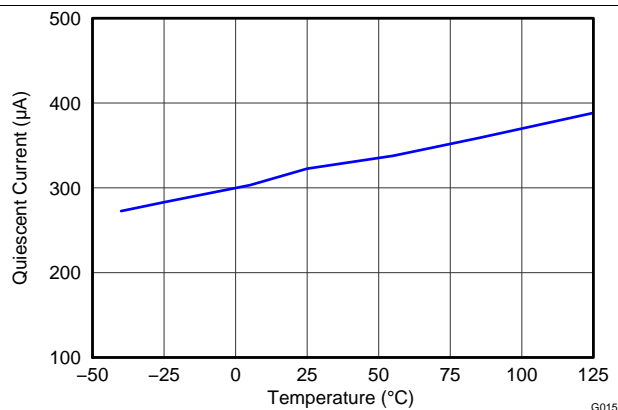


图 15. Active  $I_Q$  vs Temperature

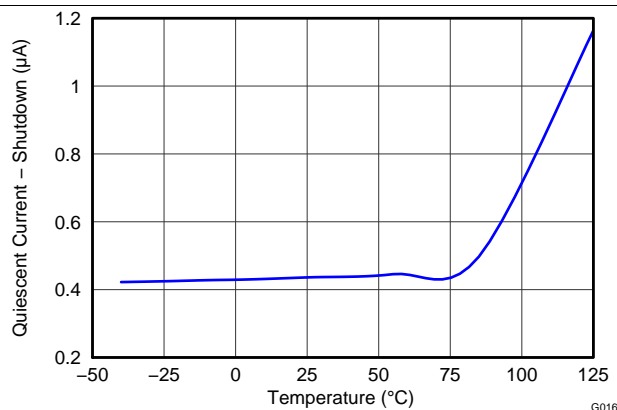


图 16. Shutdown  $I_Q$  vs Temperature

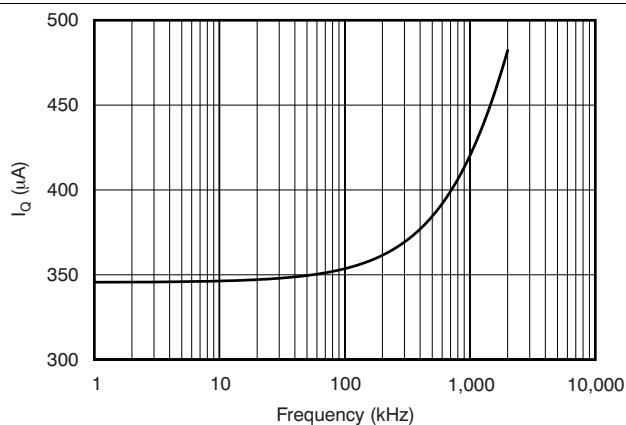


图 17. Active  $I_Q$  vs  $I^2C$  Clock Frequency

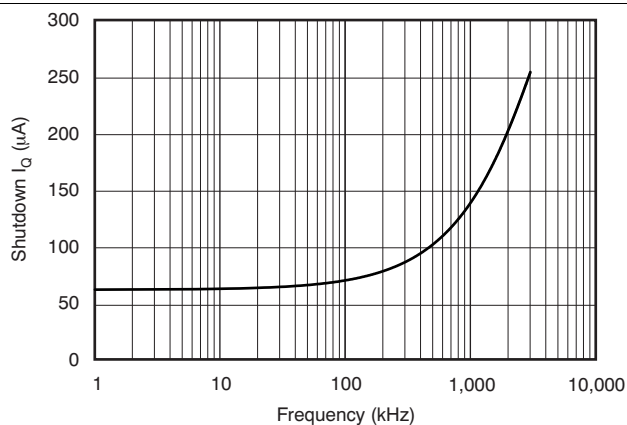


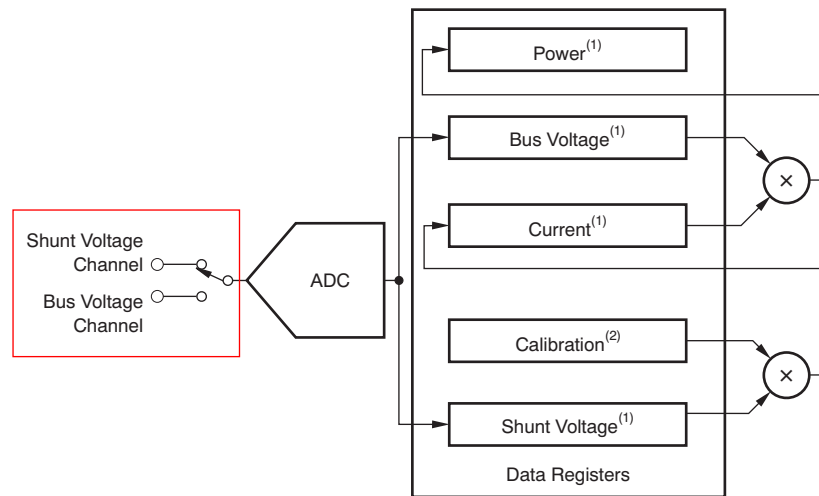
图 18. Shutdown  $I_Q$  vs  $I^2C$  Clock Frequency

## 7 Detailed Description

### 7.1 Overview

The INA226 is a digital current sense amplifier with an I<sup>2</sup>C- and SMBus-compatible interface. It provides digital current, voltage, and power readings necessary for accurate decision-making in precisely-controlled systems. Programmable registers allow flexible configuration for measurement resolution as well as continuous-versus-triggered operation. Detailed register information appears at the end of this data sheet, beginning with 表 4. See the [Functional Block Diagram](#) section for a block diagram of the INA226 device.

### 7.2 Functional Block Diagram



(1) Read-only

(2) Read/write

### 7.3 Feature Description

#### 7.3.1 Basic ADC Functions

The INA226 device performs two measurements on the power-supply bus of interest. The voltage developed from the load current that flows through a shunt resistor creates a shunt voltage that is measured at the IN+ and IN– pins. The device can also measure the power supply bus voltage by connecting this voltage to the VBUS pin. The differential shunt voltage is measured with respect to the IN– pin while the bus voltage is measured with respect to ground.

The device is typically powered by a separate supply that can range from 2.7 V to 5.5 V. The bus that is being monitored can range in voltage from 0 V to 36 V. Based on the fixed 1.25-mV LSB for the Bus Voltage Register that a full-scale register results in a 40.96 V value.

注

**Do not apply more than 36 V of actual voltage to the input pins.**

There are no special considerations for power-supply sequencing because the common-mode input range and power-supply voltage are independent of each other; therefore, the bus voltage can be present with the supply voltage off, and vice-versa.

The device takes two measurements, shunt voltage and bus voltage. It then converts these measurements to current, based on the Calibration Register value, and then calculates power. Refer to the [Programming the Calibration Register](#) section for additional information on programming the Calibration Register.

## Feature Description (接下页)

The device has two operating modes, continuous and triggered, that determine how the ADC operates following these conversions. When the device is in the normal operating mode (that is, MODE bits of the Configuration Register (00h) are set to '111'), it continuously converts a shunt voltage reading followed by a bus voltage reading. After the shunt voltage reading, the current value is calculated (based on 公式 3). This current value is then used to calculate the power result (using 公式 4). These values are subsequently stored in an accumulator, and the measurement/calculation sequence repeats until the number of averages set in the Configuration Register (00h) is reached. Following every sequence, the present set of values measured and calculated are appended to previously collected values. After all of the averaging has been completed, the final values for shunt voltage, bus voltage, current, and power are updated in the corresponding registers that can then be read. These values remain in the data output registers until they are replaced by the next fully completed conversion results. Reading the data output registers does not affect a conversion in progress.

The mode control in the Conversion Register (00h) also permits selecting modes to convert only the shunt voltage or the bus voltage in order to further allow the user to configure the monitoring function to fit the specific application requirements.

All current and power calculations are performed in the background and do not contribute to conversion time.

In triggered mode, writing any of the triggered convert modes into the Configuration Register (00h) (that is, MODE bits of the Configuration Register (00h) are set to '001', '010', or '011') triggers a single-shot conversion. This action produces a single set of measurements; thus, to trigger another single-shot conversion, the Configuration Register (00h) must be written to a second time, even if the mode does not change.

In addition to the two operating modes (continuous and triggered), the device also has a power-down mode that reduces the quiescent current and turns off current into the device inputs, reducing the impact of supply drain when the device is not being used. Full recovery from power-down mode requires 40μs. The registers of the device can be written to and read from while the device is in power-down mode. The device remains in power-down mode until one of the active modes settings are written into the Configuration Register (00h) .

Although the device can be read at any time, and the data from the last conversion remain available, the Conversion Ready flag bit (Mask/Enable Register, CVRF bit) is provided to help coordinate one-shot or triggered conversions. The Conversion Ready flag (CVRF) bit is set after all conversions, averaging, and multiplication operations are complete.

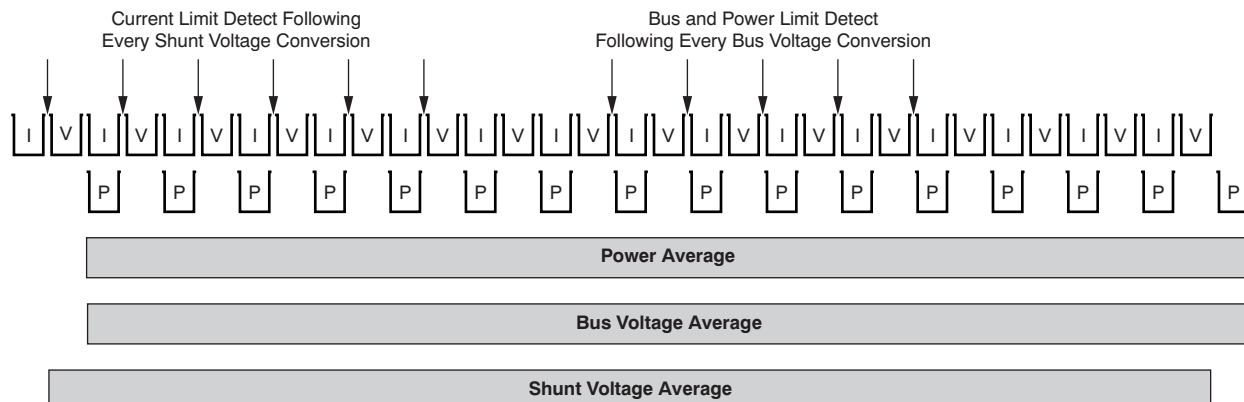
The Conversion Ready flag (CVRF) bit clears under these conditions:

- Writing to the Configuration Register (00h), except when configuring the MODE bits for power-down mode; or
- Reading the Mask/Enable Register (06h)

### 7.3.1.1 Power Calculation

The Current and Power are calculated following shunt voltage and bus voltage measurements as shown in 图 19. Current is calculated following a shunt voltage measurement based on the value set in the Calibration Register. If there is no value loaded into the Calibration Register, the current value stored is zero. Power is calculated following the bus voltage measurement based on the previous current calculation and bus voltage measurement. If there is no value loaded in the Calibration Register, the power value stored is also zero. Again, these calculations are performed in the background and do not add to the overall conversion time. These current and power values are considered intermediate results (unless the averaging is set to 1) and are stored in an internal accumulation register, not the corresponding output registers. Following every measured sample, the newly-calculated values for current and power are appended to this accumulation register until all of the samples have been measured and averaged based on the number of averages set in the Configuration Register (00h).

## Feature Description (接下页)



**图 19. Power Calculation Scheme**

In addition to the current and power accumulating after every sample, the shunt and bus voltage measurements are also collected. After all of the samples have been measured and the corresponding current and power calculations have been made, the accumulated average for each of these parameters is then loaded to the corresponding output registers, where they can then be read.

### 7.3.1.2 Alert Pin

The INA226 has a single Alert Limit Register (07h), that allows the Alert pin to be programmed to respond to a single user-defined event or to a Conversion Ready notification if desired. The Mask/Enable Register allows the user to select from one of the five available functions to monitor and/or set the Conversion Ready bit to control the response of the Alert pin. Based on the function being monitored, the user would then enter a value into the Alert Limit Register to set the corresponding threshold value that asserts the Alert pin.

The Alert pin allows for one of several available alert functions to be monitored to determine if a user-defined threshold has been exceeded. The five alert functions that can be monitored are:

- Shunt Voltage Over-Limit (SOL)
- Shunt Voltage Under-Limit (SUL)
- Bus Voltage Over-Limit (BOL)
- Bus Voltage Under-Limit (BUL)
- Power Over-Limit (POL)

The Alert pin is an open-drain output. This pin is asserted when the alert function selected in the Mask/Enable Register exceeds the value programmed into the Alert Limit Register. Only one of these alert functions can be enabled and monitored at a time. If multiple alert functions are enabled, the selected function in the highest significant bit position takes priority and responds to the Alert Limit Register value. For example, if the Shunt Voltage Over-Limit function and the Shunt Voltage Under-Limit function are both selected, the Alert pin asserts when the Shunt Voltage Register exceeds the value in the Alert Limit Register.

The Conversion Ready state of the device can also be monitored at the Alert pin to inform the user when the device has completed the previous conversion and is ready to begin a new conversion. Conversion Ready can be monitored at the Alert pin along with one of the alert functions. If an alert function and the Conversion Ready are both enabled to be monitored at the Alert pin, after the Alert pin is asserted, the Mask/Enable Register must be read following the alert to determine the source of the alert. By reading the Conversion Ready Flag (CVRF, bit 3), and the Alert Function Flag (AFF, bit 4) in the Mask/Enable Register, the source of the alert can be determined. If the Conversion Ready feature is not desired and the CNVR bit is not set, the Alert pin only responds to an exceeded alert limit based on the alert function enabled.

If the alert function is not used, the Alert pin can be left floating without impacting the operation of the device.

## Feature Description (接下页)

Refer to 图 19 to see the relative timing of when the value in the Alert Limit Register is compared to the corresponding converted value. For example, if the alert function that is enabled is Shunt Voltage Over-Limit (SOL), following every shunt voltage conversion the value in the Alert Limit Register is compared to the measured shunt voltage to determine if the measurements has exceeded the programmed limit. The AFF, bit 4 of the Mask/Enable Register, asserts high any time the measured voltage exceeds the value programmed into the Alert Limit Register. In addition to the AFF being asserted, the Alert pin is asserted based on the Alert Polarity Bit (APOL, bit 1 of the Mask/Enable Register). If the Alert Latch is enabled, the AFF and Alert pin remain asserted until either the Configuration Register (00h) is written to or the Mask/Enable Register is read.

The Bus Voltage alert functions compare the measured bus voltage to the Alert Limit Register following every bus voltage conversion and assert the AFF bit and Alert pin if the limit threshold is exceeded.

The Power Over-Limit alert function is also compared to the calculated power value following every bus voltage measurement conversion and asserts the AFF bit and Alert pin if the limit threshold is exceeded.

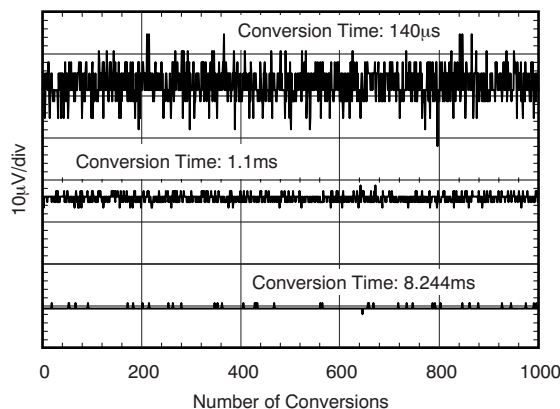
## 7.4 Device Functional Modes

### 7.4.1 Averaging and Conversion Time Considerations

The INA226 device offers programmable conversion times ( $t_{CT}$ ) for both the shunt voltage and bus voltage measurements. The conversion times for these measurements can be selected from as fast as 140  $\mu$ s to as long as 8.244 ms. The conversion time settings, along with the programmable averaging mode, allow the device to be configured to optimize the available timing requirements in a given application. For example, if a system requires that data be read every 5ms, the device could be configured with the conversion times set to 588  $\mu$ s for both shunt and bus voltage measurements and the averaging mode set to 4. This configuration results in the data updating approximately every 4.7ms. The device could also be configured with a different conversion time setting for the shunt and bus voltage measurements. This type of approach is common in applications where the bus voltage tends to be relatively stable. This situation can allow for the time focused on the bus voltage measurement to be reduced relative to the shunt voltage measurement. The shunt voltage conversion time could be set to 4.156 ms with the bus voltage conversion time set to 588  $\mu$ s, with the averaging mode set to 1. This configuration also results in data updating approximately every 4.7 ms.

There are trade-offs associated with the settings for conversion time and the averaging mode used. The averaging feature can significantly improve the measurement accuracy by effectively filtering the signal. This approach allows the device to reduce any noise in the measurement that may be caused by noise coupling into the signal. A greater number of averages enables the device to be more effective in reducing the noise component of the measurement.

The conversion times selected can also have an impact on the measurement accuracy. 图 20 shows multiple conversion times to illustrate the impact of noise on the measurement. In order to achieve the highest accuracy measurement possible, use a combination of the longest allowable conversion times and highest number of averages, based on the timing requirements of the system.



**图 20. Noise vs Conversion Time**

## Device Functional Modes (接下页)

### 7.4.2 Filtering and Input Considerations

Measuring current is often noisy, and such noise can be difficult to define. The INA226 device offers several options for filtering by allowing the conversion times and number of averages to be selected independently in the Configuration Register (00h). The conversion times can be set independently for the shunt voltage and bus voltage measurements to allow added flexibility in configuring the monitoring of the power-supply bus.

The internal ADC is based on a delta-sigma ( $\Delta\Sigma$ ) front-end with a 500 kHz ( $\pm 30\%$ ) typical sampling rate. This architecture has good inherent noise rejection; however, transients that occur at or very close to the sampling rate harmonics can cause problems. Because these signals are at 1 MHz and higher, they can be managed by incorporating filtering at the input of the device. The high frequency enables the use of low-value series resistors on the filter with negligible effects on measurement accuracy. In general, filtering the device input is only necessary if there are transients at exact harmonics of the 500 kHz ( $\pm 30\%$ ) sampling rate (greater than 1 MHz). Filter using the lowest possible series resistance (typically 10  $\Omega$  or less) and a ceramic capacitor. Recommended values for this capacitor are between 0.1  $\mu\text{F}$  and 1  $\mu\text{F}$ . 图 21 shows the device with a filter added at the input.

Overload conditions are another consideration for the device inputs. The device inputs are specified to tolerate 40 V across the inputs. A large differential scenario might be a short to ground on the load side of the shunt. This type of event can result in full power-supply voltage across the shunt (as long the power supply or energy storage capacitors support it). Removing a short to ground can result in inductive kickbacks that could exceed the 40-V differential and common-mode rating of the device. Inductive kickback voltages are best controlled by Zener-type transient-absorbing devices (commonly called *transzorb*s) combined with sufficient energy storage capacitance. See the TI Design, *Transient Robustness for Current Shunt Monitors* (TIDU473), which describes a high-side current shunt monitor used to measure the voltage developed across a current-sensing resistor when current passes through it.

In applications that do not have large energy storage electrolytics on one or both sides of the shunt, an input overstress condition may result from an excessive  $dV/dt$  of the voltage applied to the input. A hard physical short is the most likely cause of this event, particularly in applications with no large electrolytics present. This problem occurs because an excessive  $dV/dt$  can activate the ESD protection in the device in systems where large currents are available. Testing demonstrates that the addition of 10- $\Omega$  resistors in series with each input of the device sufficiently protects the inputs against this  $dV/dt$  failure up to the 40-V rating of the device. Selecting these resistors in the range noted has minimal effect on accuracy.

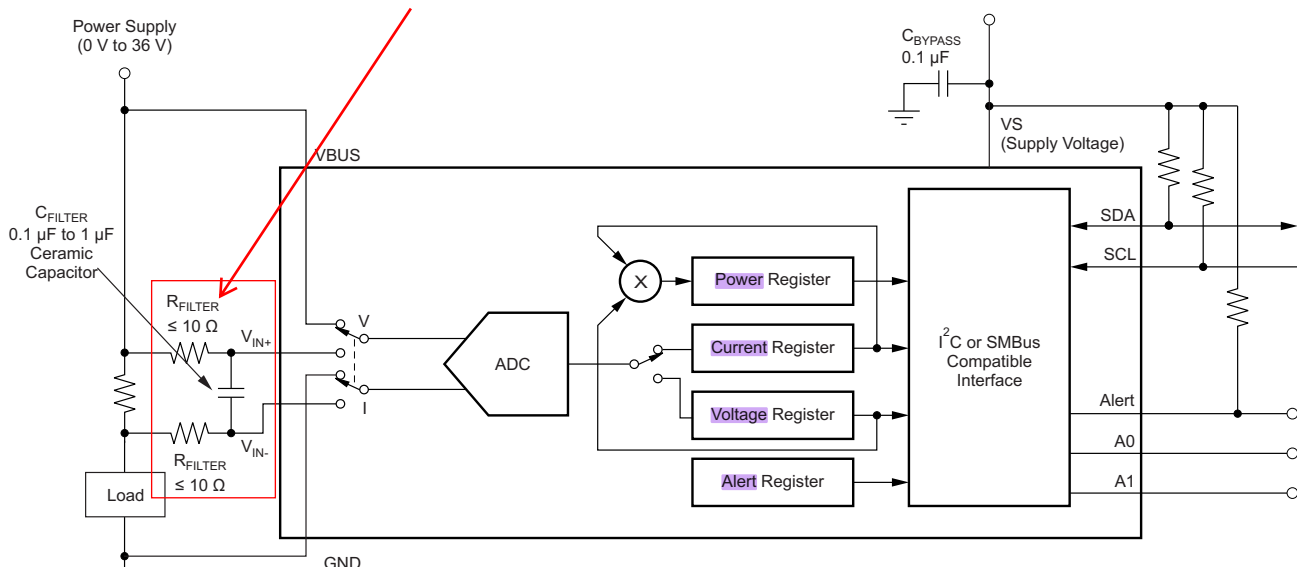


图 21. Input Filtering

测量电流通常很吵，这种噪声可能很难定义。INA226器件通过允许在配置寄存器（00h）中独立选择转换时间和平均数，提供了几种滤波选项。可以为分流电压和总线电压测量值独立设置转换时间，以便在配置电源总线的监视时增加灵活性。内部ADC基于 $\Delta\Sigma$  ( $\Delta\Sigma$ ) 前端，具有500 kHz ( $\pm 30\%$ ) 的典型采样率。这种架构具有良好的固有噪声抑制能力。但是，在采样率谐波处或非常接近采样率谐波处发生的瞬变会引起问题。由于这些信号的频率为1 MHz或更高，因此可以通过在设备的输入端合并滤波来对其进行管理。高频允许在滤波器上使用低值串联电阻，而对测量精度的影响可忽略不计。通常，仅当在500 kHz ( $\pm 30\%$ ) 采样率（大于1 MHz）的精确谐波处存在瞬变时，才需要对设备输入进行滤波。使用尽可能低的串联电阻（通常为10 $\Omega$ 或更小）和一个陶瓷电容器进行滤波。该电容器的推荐值在0.1 F至1 F之间。图21显示了在输入端添加了滤波器的设备

过载条件是设备输入的另一个考虑因素。规定设备输入的输入两端可承受40 V电压。较大的差异情况可能是分流器负载侧接地短路。这种类型的事件可能会导致分流器上的电源电压满（只要电源或储能电容器支持它）。消除对地短路会导致感性反冲，该反冲可能会超过器件的40V差分及共模额定值。电感反冲电压最好由齐纳型瞬态吸收器件（通常称为箝压器件）和足够的储能电容控制。请参见TI设计，《电流分流监控器的瞬态鲁棒性》（TIDU473），其中描述了一种高端电流分流监控器，用于测量电流流经电流传感电阻器时产生的电压。在分流器的一侧或两侧没有大量储能电解液的应用中，输入过应力情况可能是由施加到输入的电压的过大 $dV/dt$ 引起的。强烈的物理短路是导致此事件的最可能原因，尤其是在没有大量电解液的应用中。发生此问题的原因是，在可用大电流的系统中，过量的 $dV/dt$ 会激活设备中的ESD保护。测试表明，在设备的每个输入端串联一个10 $\Omega$ 电阻，足以保护输入免受高达40V额定值的 $dV/dt$ 故障的影响。在上述范围内选择这些电阻对精度的影响很小。



## 7.5 Programming

An important aspect of the INA226 device is that it does not necessarily measure current or power. The device measures both the differential voltage applied between the IN+ and IN- input pins and the voltage applied to the VBUS pin. In order for the device to report both current and power values, the user must program the resolution of the Current Register (04h) and the value of the shunt resistor present in the application to develop the differential voltage applied between the input pins. The Power Register (03h) is internally set to be 25 times the programmed Current\_LSB. Both the Current\_LSB and shunt resistor value are used in the calculation of the Calibration Register value the device uses to calculate the corresponding current and power values based on the measured shunt and bus voltages.

The Calibration Register is calculated based on 公式 1. This equation includes the term Current\_LSB, which is the programmed value for the LSB for the Current Register (04h). The user uses this value to convert the value in the Current Register (04h) to the actual current in amperes. The highest resolution for the Current Register (04h) can be obtained by using the smallest allowable Current\_LSB based on the maximum expected current as shown in 公式 2. While this value yields the highest resolution, it is common to select a value for the Current\_LSB to the nearest round number above this value to simplify the conversion of the Current Register (04h) and Power Register (03h) to amperes and watts respectively. The  $R_{SHUNT}$  term is the value of the external shunt used to develop the differential voltage across the input pins.

$$CAL = \frac{0.00512}{Current\_LSB \cdot R_{SHUNT}}$$

where

- 0.00512 is an internal fixed value used to ensure scaling is maintained properly (1)

$$Current\_LSB = \frac{Maximum\ Expected\ Current}{2^{15}} \quad (2)$$

After programming the Calibration Register, the Current Register (04h) and Power Register (03h) update accordingly based on the corresponding shunt voltage and bus voltage measurements. Until the Calibration Register is programmed, the Current Register (04h) and Power Register (03h) remain at zero.

### 7.5.1 Programming the Calibration Register

图 27 shows a nominal 10-A load that creates a differential voltage of 20 mV across a 2-mΩ shunt resistor. The bus voltage for the INA226 is measured at the external VBUS input pin, which in this example is connected to the IN- pin to measure the voltage level delivered to the load. For this example, the VBUS pin measures less than 12 V because the voltage at the IN- pin is 11.98 V as a result of the voltage drop across the shunt resistor.

For this example, assuming a maximum expected current of 15 A, the Current\_LSB is calculated to be 457.7 μA/bit using 公式 2. Using a value for the Current\_LSB of 500 μA/Bit or 1 mA/Bit would significantly simplify the conversion from the Current Register (04h) and Power Register (03h) to amperes and watts. For this example, a value of 1 mA/bit was chosen for the Current\_LSB. Using this value for the Current\_LSB does trade a small amount of resolution for having a simpler conversion process on the user side. Using 公式 1 in this example with a Current\_LSB value of 1 mA/bit and a shunt resistor of 2 mΩ results in a Calibration Register value of 2560, or A00h.

The Current Register (04h) is then calculated by multiplying the decimal value of the Shunt Voltage Register (01h) contents by the decimal value of the Calibration Register and then dividing by 2048, as shown in 公式 3. For this example, the Shunt Voltage Register contains a value of 8,000 (representing 20 mV), which is multiplied by the Calibration Register value of 2560 and then divided by 2048 to yield a decimal value for the Current Register (04h) of 10000, or 2710h. Multiplying this value by 1 mA/bit results in the original 10-A level stated in the example.

$$Current = \frac{ShuntVoltage \cdot CalibrationRegister}{2048} \quad (3)$$

## Programming (接下页)

The LSB for the Bus Voltage Register (02h) is a fixed 1.25 mV/bit, which means that the 11.98 V present at the VBUS pin results in a register value of 2570h, or a decimal equivalent of 9584. Note that the MSB of the Bus Voltage Register (02h) is always zero because the VBUS pin is only able to measure positive voltages.

The Power Register (03h) is then be calculated by multiplying the decimal value of the Current Register, 10000, by the decimal value of the Bus Voltage Register (02h), 9584, and then dividing by 20,000, as defined in 公式 4. For this example, the result for the Power Register (03h) is 12B8h, or a decimal equivalent of 4792. Multiplying this result by the power LSB (25 times the  $[1 \times 10^{-3}$  Current\_LSB]) results in a power calculation of  $(4792 \times 25$  mW/bit), or 119.82 W. The power LSB has a fixed ratio to the Current\_LSB of 25. For this example, a programmed 1 mA/bit Current\_LSB results in a power LSB of 25 mW/bit. This ratio is internally programmed to ensure that the scaling of the power calculation is within an acceptable range. A manual calculation for the power being delivered to the load would use a bus voltage of 11.98 V ( $12 V_{CM} - 20$  mV shunt drop) multiplied by the load current of 10 A to give a result of 119.8 W.

$$\text{Power} = \frac{\text{Current} \cdot \text{BusVoltage}}{20,000} \quad (4)$$

表 1 lists the steps for configuring, measuring, and calculating the values for current and power for this device.

**表 1. Calculating Current and Power<sup>(1)</sup>**

STEP	REGISTER NAME	ADDRESS	CONTENTS	DEC	LSB	VALUE
Step 1	Configuration Register	00h	4127h	—	—	—
Step 2	Shunt Register	01h	1F40h	8000	2.5 $\mu$ V	20 mV
Step 3	Bus Voltage Register	02h	2570h	9584	1.25 mV	11.98 V
Step 4	Calibration Register	05h	A00h	2560	—	—
Step 5	Current Register	04h	2710	10000	1 mA	10 A
Step 6	Power Register	03h	12B8h	4792	25 mW	119.82 W

(1) Conditions: Load = 10 A,  $V_{CM} = 12$  V,  $R_{SHUNT} = 2$  m $\Omega$ , and  $V_{VBUS} = 12$  V.

## 7.5.2 Programming the Power Measurement Engine

### 7.5.2.1 Calibration Register and Scaling

The Calibration Register enables the user to scale the Current Register (04h) and Power Register (03h) to the most useful value for a given application. For example, set the Calibration Register such that the largest possible number is generated in the Current Register (04h) or Power Register (03h) at the expected full-scale point. This approach yields the highest resolution using the previously calculated minimum Current\_LSB in the equation for the Calibration Register. The Calibration Register can also be selected to provide values in the Current Register (04h) and Power Register (03h) that either provide direct decimal equivalents of the values being measured, or yield a round LSB value for each corresponding register. After these choices have been made, the Calibration Register also offers possibilities for end user system-level calibration. After determining the exact current by using an external ammeter, the value of the Calibration Register can then be adjusted based on the measured current result of the INA226 to cancel the total system error as shown in 公式 5.

$$\text{Corrected\_Full\_Scale\_Cal} = \text{trunc} \left( \frac{\text{Cal} \times \text{MeasShuntCurrent}}{\text{INA226\_Current}} \right) \quad (5)$$

### 7.5.3 Simple Current Shunt Monitor Usage (No Programming Necessary)

The device can be used without any programming if it is only necessary to read a shunt voltage drop and bus voltage with the default power-on reset configuration and continuous conversion of shunt and bus voltages.



Without programming the device Calibration Register, the device is unable to provide either a valid current or power value, because these outputs are both derived using the values loaded into the Calibration Register.

#### 7.5.4 Default Settings

The default power-up states of the registers are shown in the [Register Maps](#) section of this data sheet. These registers are volatile, and if programmed to a value other than the default values shown in [表 4](#), they must be re-programmed at every device power-up. Detailed information on programming the Calibration Register specifically is given in the [Programming](#) section and calculated based on [公式 1](#).

#### 7.5.5 Bus Overview

The INA226 offers compatibility with both I<sup>2</sup>C and SMBus interfaces. The I<sup>2</sup>C and SMBus protocols are essentially compatible with one another.

The I<sup>2</sup>C interface is used throughout this data sheet as the primary example, with SMBus protocol specified only when a difference between the two systems is discussed. Two lines, SCL and SDA, connect the device to the bus. Both SCL and SDA are open-drain connections.

The device that initiates a data transfer is called a *master*, and the devices controlled by the master are *slaves*. The bus must be controlled by a master device that generates the serial clock (SCL), controls the bus access, and generates START and STOP conditions.

To address a specific device, the master initiates a start condition by pulling the data signal line (SDA) from a high to a low logic level while SCL is high. All slaves on the bus shift in the slave address byte on the rising edge of SCL, with the last bit indicating whether a read or write operation is intended. During the ninth clock pulse, the slave being addressed responds to the master by generating an Acknowledge and pulling SDA low.

Data transfer is then initiated and eight bits of data are sent, followed by an *Acknowledge* bit. During data transfer, SDA must remain stable while SCL is high. Any change in SDA while SCL is high is interpreted as a start or stop condition.

After all data have been transferred, the master generates a stop condition, indicated by pulling SDA from low to high while SCL is high. The device includes a 28 ms timeout on its interface to prevent locking up the bus.

### 7.5.5.1 Serial Bus Address

To communicate with the INA226, the master must first address slave devices via a slave address byte. The slave address byte consists of seven address bits and a direction bit that indicates whether the action is to be a read or write operation.

The device has two address pins, A0 and A1. 表 2 lists the pin logic levels for each of the 16 possible addresses. The device samples the state of pins A0 and A1 on every bus communication. Establish the pin states before any activity on the interface occurs.

#### 7.5.5.1 串行总线地址

为了与INA226通信，主机必须首先通过从机地址字节对从机进行寻址。从机地址字节由七个地址位和一个方向位组成，方向位指示该操作是读操作还是写操作。器件具有两个地址引脚，A0和A1。表2列出了16种可能地址中的每一个的引脚逻辑电平。器件在每次总线通信时都会采样引脚A0和A1的状态。在接口上发生任何活动之前，请建立引脚状态。

**表 2. Address Pins and Slave Addresses**

A1	A0	SLAVE ADDRESS
GND	GND	1000000
GND	VS	1000001
GND	SDA	1000010
GND	SCL	1000011
VS	GND	1000100
VS	VS	1000101
VS	SDA	1000110
VS	SCL	1000111
SDA	GND	1001000
SDA	VS	1001001
SDA	SDA	1001010
SDA	SCL	1001011
SCL	GND	1001100
SCL	VS	1001101
SCL	SDA	1001110
SCL	SCL	1001111

INA226仅在I2C总线和SMBus上作为从设备运行。通过漏极开路SDA和SCL线连接到总线。SDA和SCL引脚具有集成的尖峰抑制滤波器和施密特触发器，以最大程度地减少输入尖峰和总线噪声的影响。尽管该设备将尖峰抑制功能集成到了数字I/O线中，但是适当的布局技术有助于最大程度地减少耦合到通信线中的数量。这种噪声的引入可能是由于两条通信线路本身之间的电容耦合信号沿或系统中存在的其他开关噪声源引起的。在印刷电路板（PCB）的各层之间与地面平行的走线通常会减少通信线路之间的耦合影响。屏蔽的通信线路减少了意外噪声耦合到数字I/O线路中的可能性，这些噪声可能被错误地解释为启动或停止命令。INA226支持快速模式（1 kHz至400 kHz）和高速模式（1 kHz至2.94 MHz）的传输协议。所有数据字节先发送最高有效字节。

### 7.5.5.2 Serial Interface

The INA226 operates only as a slave device on both the I<sup>2</sup>C bus and the SMBus. Connections to the bus are made via the open-drain SDA and SCL lines. The SDA and SCL pins feature integrated spike suppression filters and Schmitt triggers to minimize the effects of input spikes and bus noise. Although the device integrates spike suppression into the digital I/O lines, proper layout techniques help minimize the amount of coupling into the communication lines. This noise introduction could occur from capacitively coupling signal edges between the two communication lines themselves or from other switching noise sources present in the system. Routing traces in parallel with ground in between layers on a printed circuit board (PCB) typically reduces the effects of coupling between the communication lines. Shielded communication lines reduces the possibility of unintended noise coupling into the digital I/O lines that could be incorrectly interpreted as start or stop commands.

The INA226 supports the transmission protocol for fast mode (1 kHz to 400 kHz) and high-speed mode (1 kHz to 2.94 MHz). All data bytes are transmitted most significant byte first.

### 7.5.5.3 Writing to and Reading from the INA226

Accessing a specific register on the INA226 is accomplished by writing the appropriate value to the register pointer. Refer to 表 4 for a complete list of registers and corresponding addresses. The value for the register pointer (as shown in 图 25) is the first byte transferred after the slave address byte with the R/W bit low. Every write operation to the device requires a value for the register pointer.

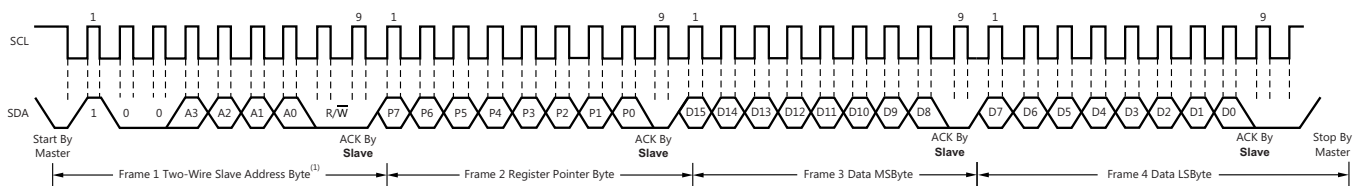
Writing to a register begins with the first byte transmitted by the master. This byte is the slave address, with the R/W bit low. The device then acknowledges receipt of a valid address. The next byte transmitted by the master is the address of the register which data is written to. This register address value updates the register pointer to the desired register. The next two bytes are written to the register addressed by the register pointer. The device acknowledges receipt of each data byte. The master may terminate data transfer by generating a start or stop condition.

When reading from the device, the last value stored in the register pointer by a write operation determines which register is read during a read operation. To change the register pointer for a read operation, a new value must be written to the register pointer. This write is accomplished by issuing a slave address byte with the R/W bit low, followed by the register pointer byte. No additional data are required. The master then generates a start condition and sends the slave address byte with the R/W bit high to initiate the read command. The next byte is transmitted by the slave and is the most significant byte of the register indicated by the register pointer. This byte is followed by an *Acknowledge* from the master; then the slave transmits the least significant byte. The master acknowledges receipt of the data byte. The master may terminate data transfer by generating a *Not-Acknowledge* after receiving any data byte, or generating a start or stop condition. If repeated reads from the same register are desired, it is not necessary to continually send the register pointer bytes; the device retains the register pointer value until it is changed by the next write operation.

图 22 shows the write operation timing diagram. 图 23 shows the read operation timing diagram.

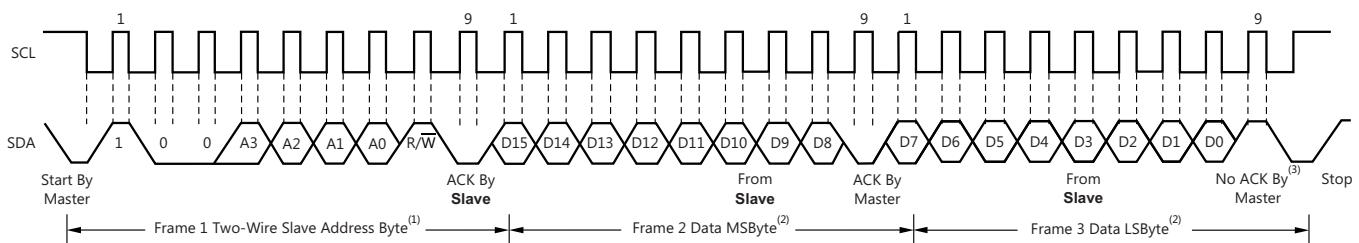
注

Register bytes are sent most-significant byte first, followed by the least significant byte.



- (1) The value of the Slave Address byte is determined by the settings of the A0 and A1 pins. Refer to 表 2.

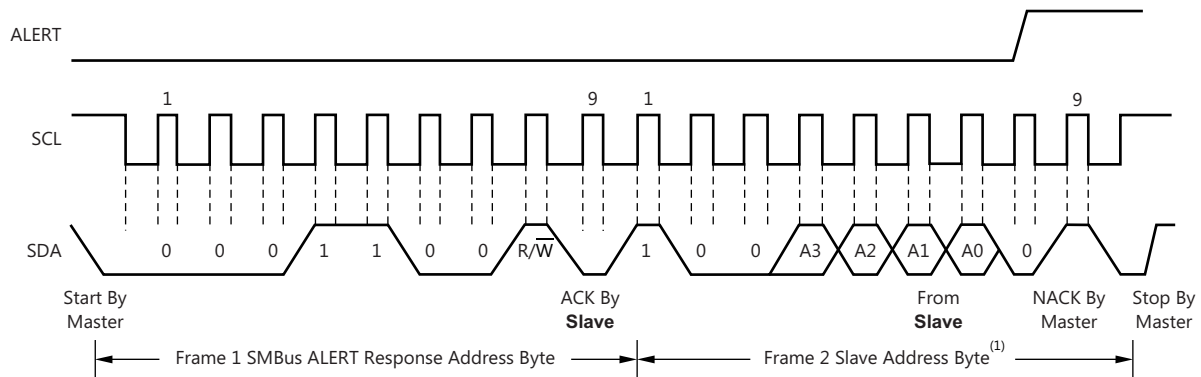
图 22. Timing Diagram for Write Word Format



- (1) The value of the Slave Address byte is determined by the settings of the A0 and A1 pins. Refer to 表 2.  
 (2) Read data is from the last register pointer location. If a new register is desired, the register pointer must be updated. See 图 25.  
 (3) ACK by Master can also be sent.

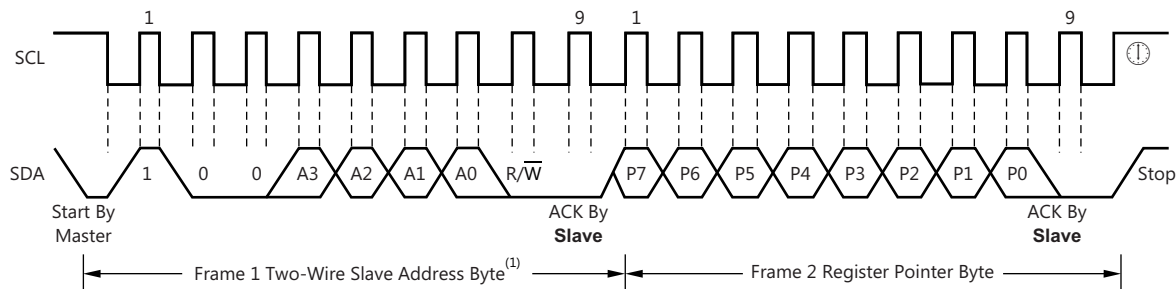
图 23. Timing Diagram for Read Word Format

图 24 shows the timing diagram for the SMBus Alert response operation. 图 25 illustrates a typical register pointer configuration.



(1) The value of the Slave Address Byte is determined by the settings of the A0 and A1 pins. Refer to 表 2.

**图 24. Timing Diagram for SMBus ALERT**



(1) The value of the Slave Address Byte is determined by the settings of the A0 and A1 pins. Refer to 表 2.

**图 25. Typical Register Pointer Set**

主机生成一个开始条件。

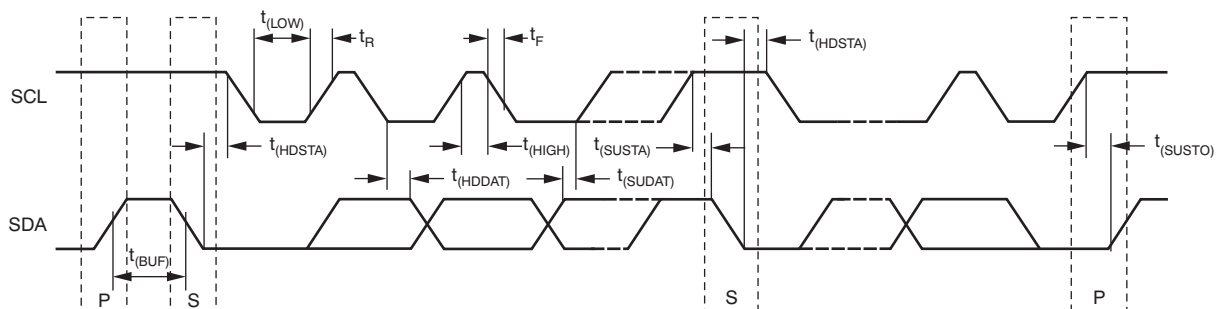
后跟一个包含快速 (HS) 主机代码 00001XXX 的有效串行字节。此传输以 400 kHz 以下的快速 (400 kHz) 或标准 (100 kHz) (F/S) 模式传输。该设备无法识别 HS 主机代码，但可以识别 HS 主机代码并切换内部滤波器以支持 2.94 MHz 操作。

#### 7.5.5.3.1 High-Speed I<sup>2</sup>C Mode

When the bus is idle, both the SDA and SCL lines are pulled high by the pullup resistors. The master generates a start condition followed by a valid serial byte containing high-speed (HS) master code 00001XXX. This transmission is made in fast (400 kHz) or standard (100 kHz) (F/S) mode at no more than 400 kHz. The device does not acknowledge the HS master code, but does recognize it and switches its internal filters to support 2.94 MHz operation.

然后，主机产生一个重复的开始条件（重复的开始条件与开始条件具有相同的时间）。在此重复的开始条件之后，该协议与 F/S 模式相同，不同之处在于允许最高 2.94 MHz 的传输速度。代替使用停止条件，使用重复的启动条件将总线固定在 HS 模式。停止条件将终止 HS 模式并切换设备的所有内部滤波器以支持 F/S 模式。

The master then generates a repeated start condition (a repeated start condition has the same timing as the start condition). After this repeated start condition, the protocol is the same as F/S mode, except that transmission speeds up to 2.94 MHz are allowed. Instead of using a stop condition, use repeated start conditions to secure the bus in HS-mode. A stop condition ends the HS-mode and switches all the internal filters of the device to support the F/S mode.



**图 26. Bus Timing Diagram**

**表 3. Bus Timing Diagram Definitions<sup>(1)</sup>**

PARAMETER		FAST MODE		HIGH-SPEED MODE		UNIT
		MIN	MAX	MIN	MAX	
SCL operating frequency	$f_{(SCL)}$	0.001	0.4	0.001	2.94	MHz
Bus free time between stop and start conditions	$t_{(BUF)}$	600		160		ns
Hold time after repeated START condition. After this period, the first clock is generated.	$t_{(HDSTA)}$	100		100		ns
Repeated start condition setup time	$t_{(SUSTA)}$	100		100		ns
STOP condition setup time	$t_{(SUSTO)}$	100		100		ns
Data hold time	$t_{(HDDAT)}$	10	900	10	100	ns
Data setup time	$t_{(SUDAT)}$	100		20		ns
SCL clock low period	$t_{(LOW)}$	1300		200		ns
SCL clock high period	$t_{(HIGH)}$	600		60		ns
Data fall time	$t_F$		300		80	ns
Clock fall time	$t_F$		300		40	ns
Clock rise time	$t_R$		300		40	ns
Clock/data rise time for $SCLK \leq 100kHz$	$t_R$		1000			ns

(1) Values based on a statistical analysis of a one-time sample of devices. Minimum and maximum values are not guaranteed and not production tested.

#### 7.5.5.4 SMBus Alert Response

The INA226 is designed to respond to the SMBus Alert Response address. The SMBus Alert Response provides a quick fault identification for simple slave devices. When an Alert occurs, the master can broadcast the Alert Response slave address (0001 100) with the Read/Write bit set high. Following this Alert Response, any slave device that generates an alert identifies itself by acknowledging the Alert Response and sending its address on the bus.

The Alert Response can activate several different slave devices simultaneously, similar to the I<sup>2</sup>C General Call. If more than one slave attempts to respond, bus arbitration rules apply. The losing device does not generate an Acknowledge and continues to hold the Alert line low until the interrupt is cleared.

## 7.6 Register Maps

The INA226 uses a bank of registers for holding configuration settings, measurement results, minimum/maximum limits, and status information. 表 4 summarizes the device registers; refer to the [Functional Block Diagram](#) section for an illustration of the registers.

All 16-bit device registers are two 8-bit bytes via the I<sup>2</sup>C interface.

INA226使用一组寄存器来保存配置设置、测量结果、最小/最大

限制和状态信息。表4总结了设备寄存器；有关寄存器的说明，请参见“功能框图”部分。通过I<sup>2</sup>C接口，所有16位设备寄存器均为两个8位字节。

**表 4. Register Set Summary**

POINTER ADDRESS	REGISTER NAME	FUNCTION	POWER-ON RESET		TYPE <sup>(1)</sup>
			BINARY	HEX	
00h	Configuration Register	All-register reset, shunt voltage and bus voltage ADC conversion times and averaging, operating mode.	01000001 00100111	4127	R/W
01h	Shunt Voltage Register	Shunt voltage measurement data.	00000000 00000000	0000	R
02h	Bus Voltage Register	Bus voltage measurement data.	00000000 00000000	0000	R
03h	Power Register <sup>(2)</sup>	Contains the value of the calculated power being delivered to the load.	00000000 00000000	0000	R
04h	Current Register <sup>(2)</sup>	Contains the value of the calculated current flowing through the shunt resistor.	00000000 00000000	0000	R

(1) Type: R = Read-Only, R/W = Read/Write.

(2) The Current Register (04h) and Power Register (03h) default to '0' because the Calibration register defaults to '0', yielding zero current and power values until the Calibration register is programmed.

## Register Maps (接下页)

**表 4. Register Set Summary (接下页)**

POINTER ADDRESS	REGISTER NAME	FUNCTION	POWER-ON RESET		TYPE <sup>(1)</sup>
			BINARY	HEX	
05h	Calibration Register	Sets full-scale range and LSB of current and power measurements. Overall system calibration.	00000000 00000000	0000	R/W
06h	Mask/Enable Register	Alert configuration and Conversion Ready flag.	00000000 00000000	0000	R/W
07h	Alert Limit Register	Contains the limit value to compare to the selected Alert function.	00000000 00000000	0000	R/W
FEh	Manufacturer ID Register	Contains unique manufacturer identification number.	0101010001001001	5449	R
FFh	Die ID Register	Contains unique die identification number.	0010001001100000	2260	R

### 7.6.1 Configuration Register (00h) (Read/Write)

**表 5. Configuration Register (00h) (Read/Write) Descriptions**

BIT NO.	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	RST	—	—	—	AVG2	AVG1	AVG0	VBUSCT2	VBUSCT1	VBUSCT0	VSHCT2	VSHCT1	VSHCT0	MODE3	MODE2	MODE1
POR VALUE	0	1	0	0	0	0	0	1	0	0	1	0	0	1	1	1

The Configuration Register settings control the operating modes for the device. This register controls the conversion time settings for both the shunt and bus voltage measurements as well as the averaging mode used. The operating mode that controls what signals are selected to be measured is also programmed in the Configuration Register .

The Configuration Register can be read from at any time without impacting or affecting the device settings or a conversion in progress. Writing to the Configuration Register halts any conversion in progress until the write sequence is completed resulting in a new conversion starting based on the new contents of the Configuration Register (00h). This halt prevents any uncertainty in the conditions used for the next completed conversion.

**RST:**

Bit 15

**Reset Bit**

Setting this bit to '1' generates a system reset that is the same as power-on reset. Resets all registers to default values; this bit self-clears.

**AVG:**

Bits 9–11

**Averaging Mode**

Determines the number of samples that are collected and averaged. 表 6 shows all the AVG bit settings and related number of averages for each bit setting.

**表 6. AVG Bit Settings[11:9] Combinations**

AVG2 D11	AVG1 D10	AVG0 D9	NUMBER OF AVERAGES <sup>(1)</sup>
0	0	0	1
0	0	1	4
0	1	0	16
0	1	1	64
1	0	0	128
1	0	1	256
1	1	0	512
1	1	1	1024

(1) Shaded values are default.

**VBUSCT:**

Bits 6–8

**Bus Voltage Conversion Time**

Sets the conversion time for the bus voltage measurement. 表 7 shows the VBUSCT bit options and related conversion times for each bit setting.

**表 7. VBUSCT Bit Settings [8:6] Combinations**

VBUSCT2 D8	VBUSCT1 D7	VBUSCT0 D6	CONVERSION TIME <sup>(1)</sup>
0	0	0	140 $\mu$ s
0	0	1	204 $\mu$ s
0	1	0	332 $\mu$ s
0	1	1	588 $\mu$ s
1	0	0	1.1 ms
1	0	1	2.116 ms
1	1	0	4.156 ms
1	1	1	8.244 ms

(1) Shaded values are default.

**VSHCT:**

Bits 3–5

**Shunt Voltage Conversion Time**

Sets the conversion time for the shunt voltage measurement. 表 8 shows the VSHCT bit options and related conversion times for each bit setting.

**表 8. VSHCT Bit Settings [5:3] Combinations**

VSHCT2 D8	VSHCT1 D7	VSHCT0 D6	CONVERSION TIME <sup>(1)</sup>
0	0	0	140 $\mu$ s
0	0	1	204 $\mu$ s
0	1	0	332 $\mu$ s
0	1	1	588 $\mu$ s
1	0	0	1.1 ms
1	0	1	2.116 ms
1	1	0	4.156 ms
1	1	1	8.244 ms

(1) Shaded values are default.

**MODE:**

Bits 0-2

**Operating Mode**

Selects continuous, triggered, or power-down mode of operation. These bits default to continuous shunt and bus measurement mode. The mode settings are shown in 表 9.

**表 9. Mode Settings [2:0] Combinations**

MODE3 D2	MODE2 D1	MODE1 D0	MODE <sup>(1)</sup>
0	0	0	Power-Down (or Shutdown)
0	0	1	Shunt Voltage, Triggered
0	1	0	Bus Voltage, Triggered
0	1	1	Shunt and Bus, Triggered
1	0	0	Power-Down (or Shutdown)
1	0	1	Shunt Voltage, Continuous
1	1	0	Bus Voltage, Continuous
1	1	1	Shunt and Bus, Continuous

(1) Shaded values are default.

### 7.6.2 Shunt Voltage Register (01h) (Read-Only)

The Shunt Voltage Register stores the current shunt voltage reading,  $V_{SHUNT}$ . Negative numbers are represented in two's complement format. Generate the two's complement of a negative number by complementing the absolute value binary number and adding 1. An MSB = '1' denotes a negative number.

**Example:** For a value of  $V_{SHUNT} = -80$  mV:

1. Take the absolute value: 80 mV
2. Translate this number to a whole decimal number ( $80 \text{ mV} \div 2.5 \mu\text{V} = 32000$ )
3. Convert this number to binary = 0111 1101 0000 0000
4. Complement the binary result = 1000 0010 1111 1111
5. Add '1' to the complement to create the two's complement result = 1000 0011 0000 0000 = 8300h

If averaging is enabled, this register displays the averaged value.

Full-scale range = 81.92 mV (decimal = 7FFF); LSB: 2.5  $\mu\text{V}$ .

**表 10. Shunt Voltage Register (01h) (Read-Only) Description**

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	SIGN	SD14	SD13	SD12	SD11	SD10	SD9	SD8	SD7	SD6	SD5	SD4	SD3	SD2	SD1	SD0
POR VALUE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

### 7.6.3 Bus Voltage Register (02h) (Read-Only) <sup>(1)</sup>

The Bus Voltage Register stores the most recent bus voltage reading,  $V_{BUS}$ .

If averaging is enabled, this register displays the averaged value.

Full-scale range = 40.96 V (decimal = 7FFF); LSB = 1.25 mV.

**表 11. Bus Voltage Register (02h) (Read-Only) Description**

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	—	BD14	BD13	BD12	BD11	BD10	BD9	BD8	BD7	BD6	BD5	BD4	BD3	BD2	BD1	BD0
POR VALUE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

(1) D15 is always zero because bus voltage can only be positive.

### 7.6.4 Power Register (03h) (Read-Only)

If averaging is enabled, this register displays the averaged value.

The Power Register LSB is internally programmed to equal 25 times the programmed value of the Current\_LSB.

The Power Register records power in Watts by multiplying the decimal values of the Current Register with the decimal value of the Bus Voltage Register according to [公式 4](#).

**表 12. Power Register (03h) (Read-Only) Description**

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	PD15	PD14	PD13	PD12	PD11	PD10	PD9	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
POR VALUE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

### 7.6.5 Current Register (04h) (Read-Only)

If averaging is enabled, this register displays the averaged value.

The value of the Current Register is calculated by multiplying the decimal value in the Shunt Voltage Register with the decimal value of the Calibration Register, according to [公式 3](#).



**表 13. Current Register (04h) (Read-Only) Register Description**

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	CSIGN	CD14	CD13	CD12	CD11	CD10	CD9	CD8	CD7	CD6	CD5	CD4	CD3	CD2	CD1	CD0
POR VALUE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

### 7.6.6 Calibration Register (05h) (Read/Write)

This register provides the device with the value of the shunt resistor that was present to create the measured differential voltage. It also sets the resolution of the Current Register. Programming this register sets the Current\_LSB and the Power\_LSB. This register is also suitable for use in overall system calibration. See the [Programming the Calibration Register](#) for additional information on programming the Calibration Register.

**表 14. Calibration Register (05h) (Read/Write) Description**

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	—	FS14	FS13	FS12	FS11	FS10	FS9	FS8	FS7	FS6	FS5	FS4	FS3	FS2	FS1	FS0
POR VALUE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

### 7.6.7 Mask/Enable Register (06h) (Read/Write)

The Mask/Enable Register selects the function that is enabled to control the Alert pin as well as how that pin functions. If multiple functions are enabled, the highest significant bit position Alert Function (D15-D11) takes priority and responds to the Alert Limit Register.

**表 15. Mask/Enable Register (06h) (Read/Write)**

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	SOL	SUL	BOL	BUL	POL	CNVR	—	—	—	—	—	AFF	CVRF	OVF	APOL	LEN
POR VALUE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

**SOL: Shunt Voltage Over-Voltage**

Bit 15 Setting this bit high configures the Alert pin to be asserted if the shunt voltage measurement following a conversion exceeds the value programmed in the Alert Limit Register.

**SUL: Shunt Voltage Under-Voltage**

Bit 14 Setting this bit high configures the Alert pin to be asserted if the shunt voltage measurement following a conversion drops below the value programmed in the Alert Limit Register.

**BOL: Bus Voltage Over-Voltage**

Bit 13 Setting this bit high configures the Alert pin to be asserted if the bus voltage measurement following a conversion exceeds the value programmed in the Alert Limit Register.

**BUL: Bus Voltage Under-Voltage**

Bit 12 Setting this bit high configures the Alert pin to be asserted if the bus voltage measurement following a conversion drops below the value programmed in the Alert Limit Register.

**POL: Power Over-Limit**

Bit 11 Setting this bit high configures the Alert pin to be asserted if the Power calculation made following a bus voltage measurement exceeds the value programmed in the Alert Limit Register.

**CNVR: Conversion Ready**

Bit 10 Setting this bit high configures the Alert pin to be asserted when the Conversion Ready Flag, Bit 3, is asserted indicating that the device is ready for the next conversion.

**AFF: Alert Function Flag**

Bit 4

While only one Alert Function can be monitored at the Alert pin at a time, the Conversion Ready can also be enabled to assert the Alert pin. Reading the Alert Function Flag following an alert allows the user to determine if the Alert Function was the source of the Alert.

When the Alert Latch Enable bit is set to Latch mode, the Alert Function Flag bit clears only when the Mask/Enable Register is read. When the Alert Latch Enable bit is set to Transparent mode, the Alert Function Flag bit is cleared following the next conversion that does not result in an Alert condition.

**CVRF: Conversion Ready Flag**

Bit 3

Although the device can be read at any time, and the data from the last conversion is available, the Conversion Ready Flag bit is provided to help coordinate one-shot or triggered conversions. The Conversion Ready Flag bit is set after all conversions, averaging, and multiplications are complete. Conversion Ready Flag bit clears under the following conditions:

- 1.) Writing to the Configuration Register (except for Power-Down selection)
- 2.) Reading the Mask/Enable Register

**OVF: Math Overflow Flag**

Bit 2

This bit is set to '1' if an arithmetic operation resulted in an overflow error. It indicates that current and power data may be invalid.

**APOL: Alert Polarity bit; sets the Alert pin polarity.**

Bit 1

1 = Inverted (active-high open collector)  
0 = Normal (active-low open collector) (default)

**LEN: Alert Latch Enable; configures the latching feature of the Alert pin and Alert Flag bits.**

Bit 0

1 = Latch enabled  
0 = Transparent (default)

When the Alert Latch Enable bit is set to Transparent mode, the Alert pin and Flag bit resets to the idle states when the fault has been cleared. When the Alert Latch Enable bit is set to Latch mode, the Alert pin and Alert Flag bit remains active following a fault until the Mask/Enable Register has been read.

### 7.6.8 Alert Limit Register (07h) (Read/Write)

The Alert Limit Register contains the value used to compare to the register selected in the Mask/Enable Register to determine if a limit has been exceeded.

**表 16. Alert Limit Register (07h) (Read/Write) Description**

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	AUL15	AUL14	AUL13	AUL12	AUL11	AUL10	AUL9	AUL8	AUL7	AUL6	AUL5	AUL4	AUL3	AUL2	AUL1	AUL0
POR VALUE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

### 7.6.9 Manufacturer ID Register (FEh) (Read-Only)

The Manufacturer ID Register stores a unique identification number for the manufacturer.

**表 17. Manufacturer ID Register (FEh) (Read-Only) Description**

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	ID15	ID14	ID13	ID12	ID11	ID10	ID9	ID8	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0
POR VALUE	0	1	0	1	0	1	0	0	0	1	0	0	1	0	0	1

**ID: Manufacturer ID Bits**

Bits 0-15

Stores the manufacturer identification bits

### 7.6.10 Die ID Register (FFh) (Read-Only)

The Die ID Register stores a unique identification number and the revision ID for the die.

**表 18. Die ID Register (FFh) (Read-Only) Description**

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	DID11	DID10	DID9	DID8	DID7	DID6	DID5	DID4	DID3	DID2	DID1	DID0	RID3	RID2	RID1	RID0
POR VALUE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

**DID:**
**Device ID Bits**

Bits 4-15

Stores the device identification bits

**RID:**
**Die Revision ID Bits**

Bit 0-3

Stores the device revision identification bits

## 8 Application and Implementation

### 注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Validate and test the design implementation to confirm system functionality.

### 8.1 Application Information

The INA226 is a current shunt and power monitor with an I<sup>2</sup>C™ compatible interface. The device monitors both a shunt voltage drop and bus supply voltage. Programmable calibration value, conversion times, and averaging, combined with an internal multiplier, enable direct readouts of current in amperes and power in watts.

### 8.2 Typical Applications

#### 8.2.1 High-Side Sensing Circuit Application 高端检测电路应用

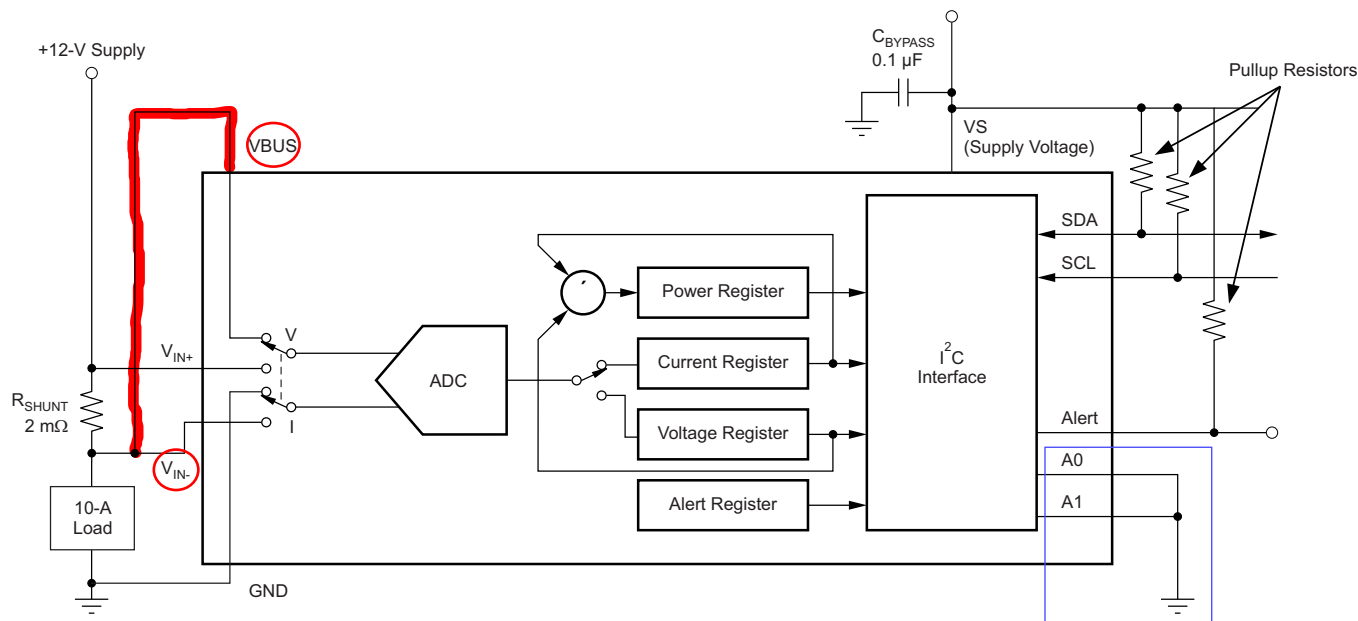


图 27. Typical Circuit Configuration, INA226

##### 8.2.1.1 Design Requirements

INA226 measures the voltage developed across a current-sensing resistor ( $R_{SHUNT}$ ) when current passes through it. The device also measures the bus supply voltage and can calculate power when calibrated. It comes with alert capability where the alert pin can be programmed to respond to a user-defined event or to a conversion ready notification. This design illustrates the ability of the alert pin to respond to a set threshold.

## Typical Applications (接下页)

### 8.2.1.2 Detailed Design Procedure

The Alert pin can be configured to respond to one of the five alert functions described in the [Alert Pin](#) section. The alert pin must to be pulled up to the  $V_{VS}$  pin voltage via the pull-up resistors. The configuration register is set based on the required conversion time and averaging. The Mask/Enable Register is set to identify the required alert function and the Alert Limit Register is set to the limit value used for comparison.

### 8.2.1.3 Application Curves

图 28 shows the Alert pin response to a shunt voltage over-limit of 80 mV for a conversion time ( $t_{CT}$ ) of 1.1 ms and averaging set to 1. 图 29 shows the response for the same limit but with the conversion time reduced to 140  $\mu$ s.

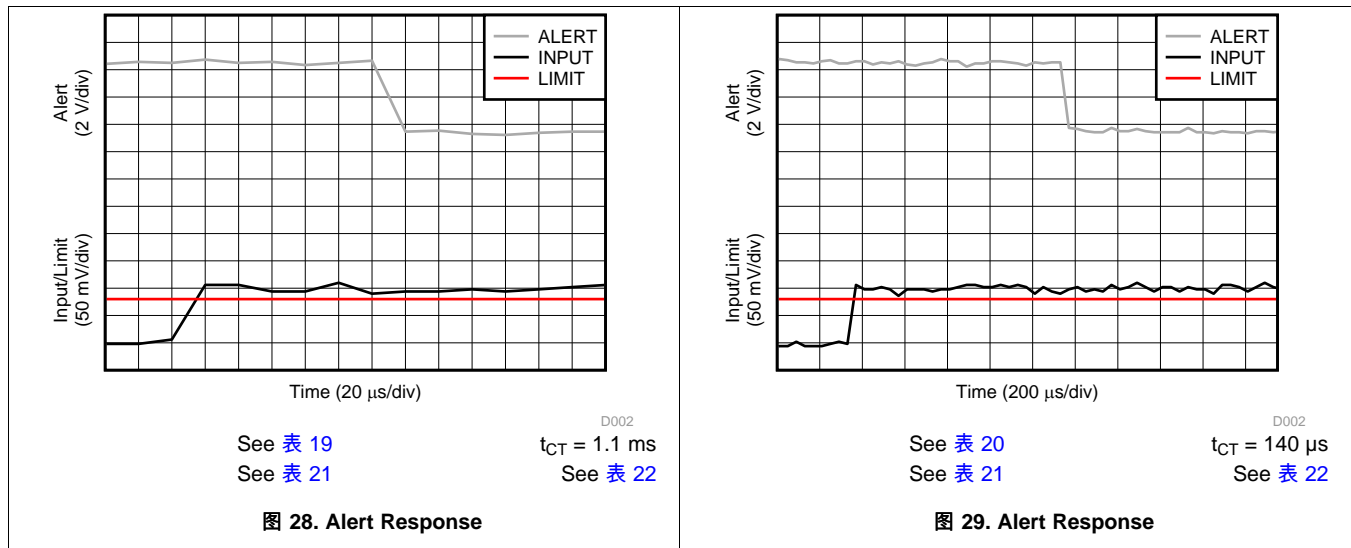


表 19. Configuration Register (00h) Settings for 图 28 (Value = 4025h)

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	RST	—	—	—	AVG2	AVG1	AVG0	VBUSC T2	VBUSC T1	VBUSC T0	V <sub>SH</sub> CT2	V <sub>SH</sub> CT1	V <sub>SH</sub> CT0	MODE3	MODE2	MODE1
POR VALUE	0	1	0	0	0	0	0	0	0	0	1	0	0	1	0	1

表 20. Configuration Register (00h) Settings for 图 29 (Value = 4005h)

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	RST	—	—	—	AVG2	AVG1	AVG0	VBUSC T2	VBUSC T1	VBUSC T0	V <sub>SH</sub> CT2	V <sub>SH</sub> CT1	V <sub>SH</sub> CT0	MODE3	MODE2	MODE1
POR VALUE	0	1	0	0	0	0	0	0	0	0	0	0	0	1	0	1

表 21. Mask/Enable Register (06h) Settings for 图 28 and 图 29 (Value = 8000h)

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	SOL	SUL	BOL	BUL	POL	CNVR	—	—	—	—	—	AFF	CVRF	OVF	APOL	LEN
POR VALUE	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

表 22. Alert Limit Register (07h) Settings for 图 28 and 图 29 (Value = 7D00)

BIT #	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
BIT NAME	AUL15	AUL14	AUL13	AUL12	AUL11	AUL10	AUL9	AUL8	AUL7	AUL6	AUL5	AUL4	AUL3	AUL2	AUL1	AUL0
POR VALUE	0	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0

## 9 Power Supply Recommendations

The input circuitry of the device can accurately measure signals on common-mode voltages beyond its power supply voltage,  $V_{VS}$ . For example, the voltage applied to the  $V_{VS}$  power supply terminal can be 5 V, whereas the load power-supply voltage being monitored (the common-mode voltage) can be as high as 36 V. Note also that the device can withstand the full 0-V to 36-V range at the input terminals, regardless of whether the device has power applied or not.

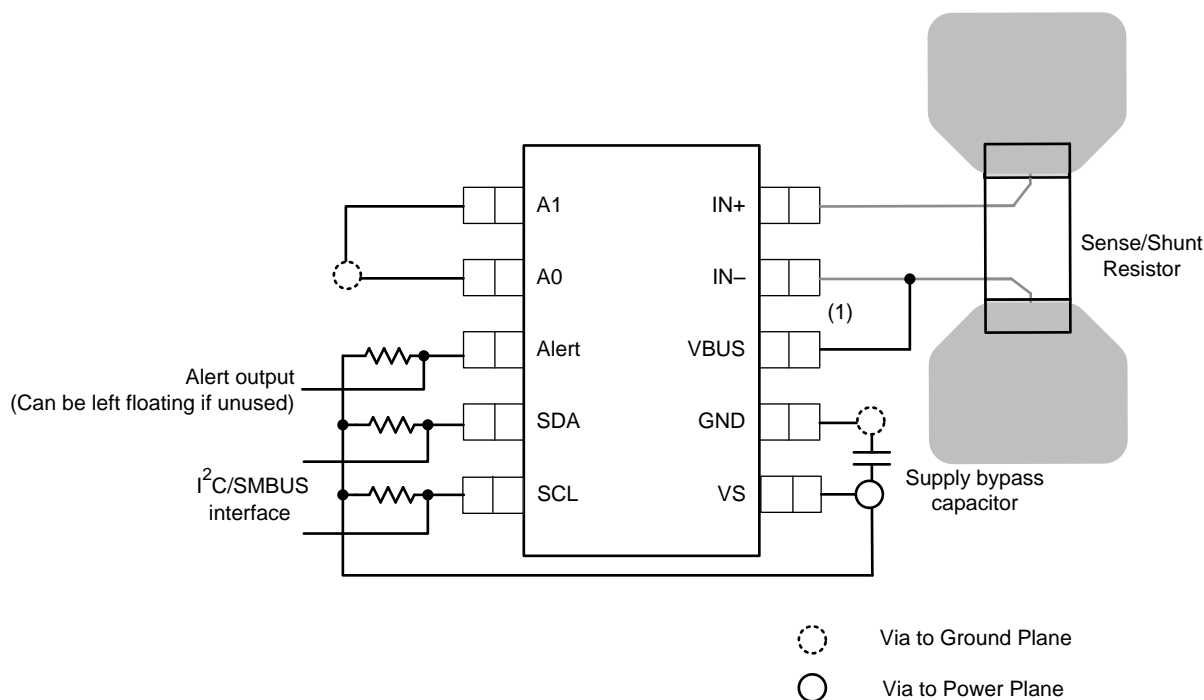
Place the required power-supply bypass capacitors as close as possible to the supply and ground terminals of the device to ensure stability. A typical value for this supply bypass capacitor is 0.1  $\mu\text{F}$ . Applications with noisy or high-impedance power supplies may require additional decoupling capacitors to reject power-supply noise.

## 10 Layout

### 10.1 Layout Guidelines

Connect the input pins (IN+ and IN-) to the sensing resistor using a Kelvin connection or a 4-wire connection. These connection techniques ensure that only the current-sensing resistor impedance is detected between the input pins. Poor routing of the current-sensing resistor commonly results in additional resistance present between the input pins. Given the very low ohmic value of the current-sensing resistor, any additional high-current carrying impedance causes significant measurement errors. Place the power-supply bypass capacitor as close as possible to the supply and ground pins.

### 10.2 Layout Example



(1) connect the VBUS pin to the power supply rail.

**图 30. INA226 Layout Example**

## 11 器件和文档支持

### 11.1 器件支持

#### 11.1.1 开发支持

- 《INA226EVM 评估板和软件教程》（文献编号：SBOU113）

### 11.2 社区资源

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

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### 11.4 静电放电警告



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### 11.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。 这些信息是针对指定器件可提供的最新数据。 这些数据会在无通知且不  
对本文档进行修订的情况下发生改变。 欲获得该数据表的浏览器版本，请查阅左侧的导航栏。

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	产品		应用
数字音频	<a href="http://www.ti.com.cn/audio">www.ti.com.cn/audio</a>	通信与电信	<a href="http://www.ti.com.cn/telecom">www.ti.com.cn/telecom</a>
放大器和线性器件	<a href="http://www.ti.com.cn/amplifiers">www.ti.com.cn/amplifiers</a>	计算机及周边	<a href="http://www.ti.com.cn/computer">www.ti.com.cn/computer</a>
数据转换器	<a href="http://www.ti.com.cn/dataconverters">www.ti.com.cn/dataconverters</a>	消费电子	<a href="http://www.ti.com.cn/consumer-apps">www.ti.com.cn/consumer-apps</a>
DLP® 产品	<a href="http://www.dlp.com">www.dlp.com</a>	能源	<a href="http://www.ti.com.cn/energy">www.ti.com.cn/energy</a>
DSP - 数字信号处理器	<a href="http://www.ti.com.cn/dsp">www.ti.com.cn/dsp</a>	工业应用	<a href="http://www.ti.com.cn/industrial">www.ti.com.cn/industrial</a>
时钟和计时器	<a href="http://www.ti.com.cn/clockandtimers">www.ti.com.cn/clockandtimers</a>	医疗电子	<a href="http://www.ti.com.cn/medical">www.ti.com.cn/medical</a>
接口	<a href="http://www.ti.com.cn/interface">www.ti.com.cn/interface</a>	安防应用	<a href="http://www.ti.com.cn/security">www.ti.com.cn/security</a>
逻辑	<a href="http://www.ti.com.cn/logic">www.ti.com.cn/logic</a>	汽车电子	<a href="http://www.ti.com.cn/automotive">www.ti.com.cn/automotive</a>
电源管理	<a href="http://www.ti.com.cn/power">www.ti.com.cn/power</a>	视频和影像	<a href="http://www.ti.com.cn/video">www.ti.com.cn/video</a>
微控制器 (MCU)	<a href="http://www.ti.com.cn/microcontrollers">www.ti.com.cn/microcontrollers</a>		
RFID 系统	<a href="http://www.ti.com.cn/rfidsys">www.ti.com.cn/rfidsys</a>		
OMAP应用处理器	<a href="http://www.ti.com.cn/omap">www.ti.com.cn/omap</a>		
无线连通性	<a href="http://www.ti.com.cn/wirelessconnectivity">www.ti.com.cn/wirelessconnectivity</a>	德州仪器在线技术支持社区	<a href="http://www.deyisupport.com">www.deyisupport.com</a>

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## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
INA226AIDGSR	ACTIVE	VSSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	226	<a href="#">Samples</a>
INA226AIDGST	ACTIVE	VSSOP	DGS	10	250	Green (RoHS & no Sb/Br)	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	226	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

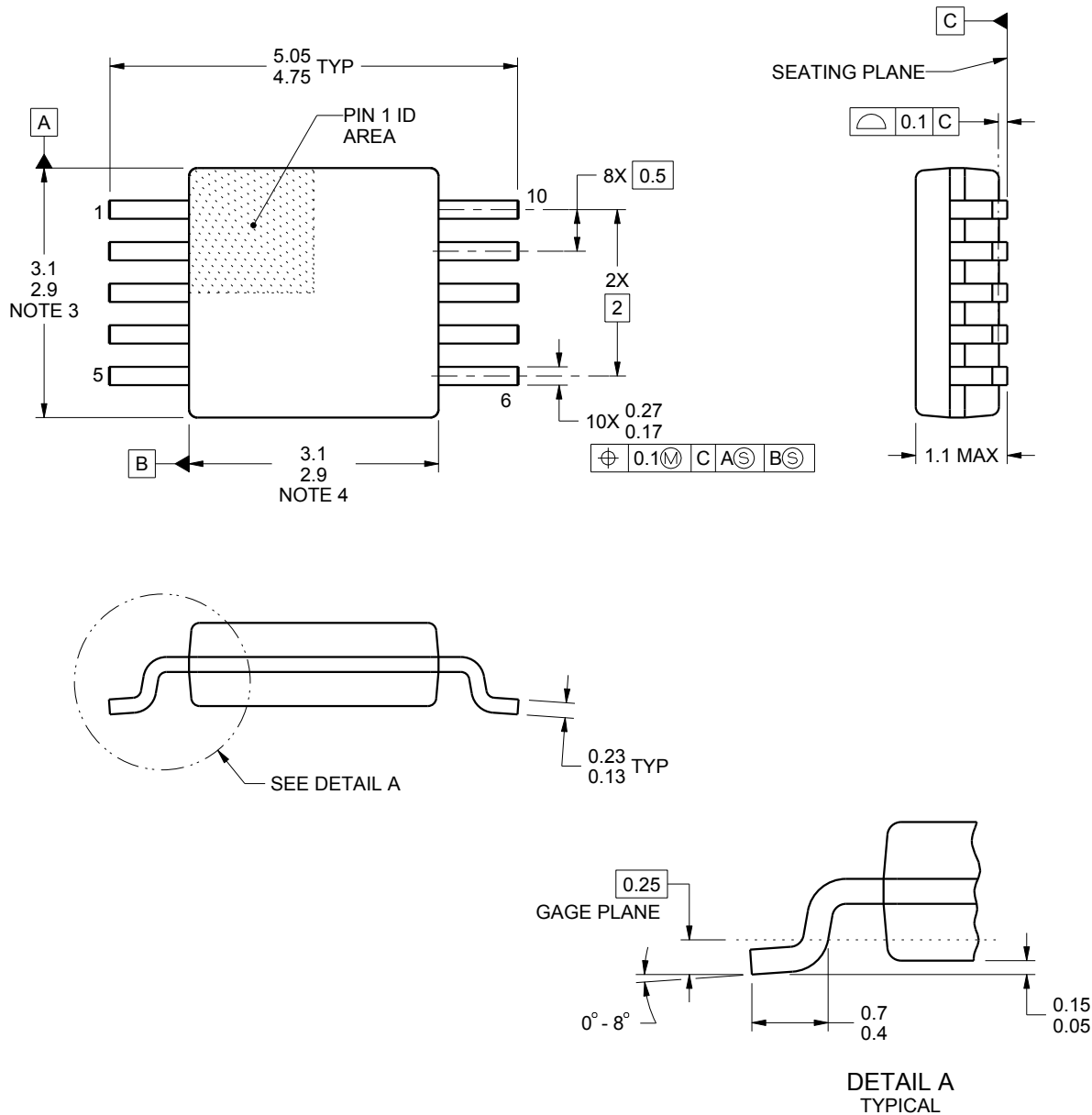
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA226AIDGSR	VSSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
INA226AIDGST	VSSOP	DGS	10	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA226AIDGSR	VSSOP	DGS	10	2500	366.0	364.0	50.0
INA226AIDGST	VSSOP	DGS	10	250	366.0	364.0	50.0



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**NOTES:**

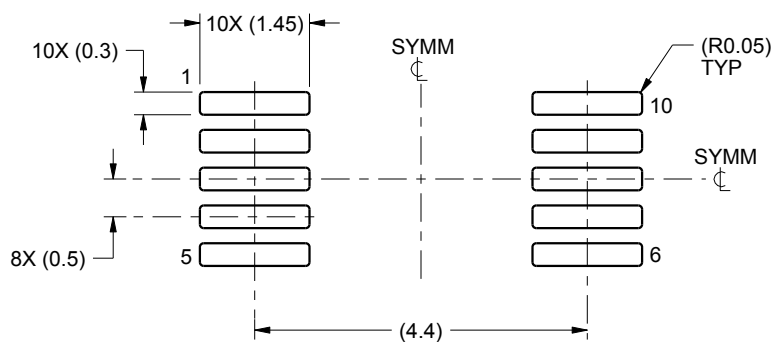
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187, variation BA.

# EXAMPLE BOARD LAYOUT

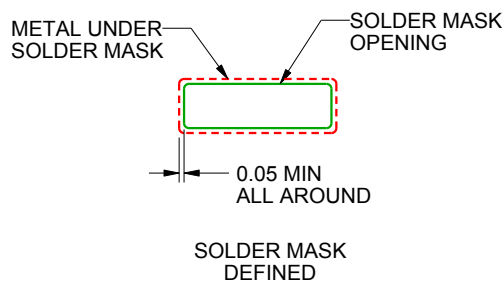
DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:10X



SOLDER MASK DETAILS  
NOT TO SCALE

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

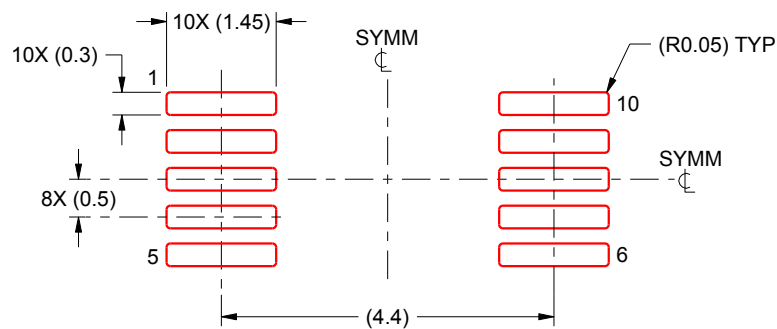
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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